HP Pro Mini 400 G9 Desktop PC



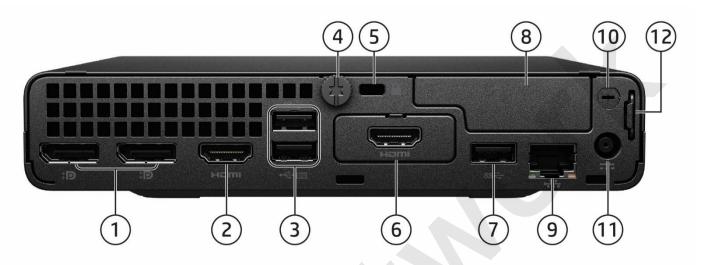
- 1. Type-C[®] SuperSpeed USB 20Gbps signaling rate port (charge support up to 5V/3A)
- 2. Type-A SuperSpeed USB 10Gbps signaling rate port
- 3. Type-A SuperSpeed USB 10Gbps signaling rate port (charge support up to 5V/1.5A)
- 4. Combo Audio Jack with CTIA and OMTP and headset support
- 5. Dual-state power button
- Hard drive activity light

Not shown

- (2) M.2 (1 as M.2 2230 socket for WLAN/BT and 1 as M.2 2280 socket for storage)
- (1) 2.5" internal storage drive bay



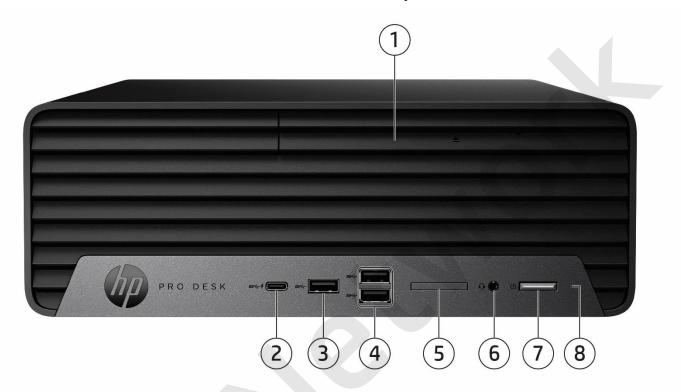
HP Pro Mini 400 G9 Desktop PC



- 1. 2x Dual Mode DisplayPort™ 1.4a(DP++)
- 2. HDMI 2.1
- 2x Type-A SuperSpeed USB 5Gbps signaling rate port (Supporting wake from S4/S5 with keyboard/mouse connected and enabled in BIOS)
- 4. Cover release thumbscrew
- 5. Standard cable lock slot (10 mm)
- 6. Flex Port 1, choice of:
 - DisplayPort™1.4a
 VGA
 with HBR3
 Serial¹
 - HDMI 2.0a
 - Type-C® SuperSpeed USB 10Gbps signaling rate port w/ DisplayPort™ Alt Mode and power intake via USB Type-C® Power Delivery up to 100W
- 1. Sold separately or as an optional feature.
- 2. Must be configured at time of purchase.

- 7. Type-A SuperSpeed USB 10Gbps signaling rate port
- 8. Flex Port 2², choice of:
 - 2x Type-A Hi-Speed USB 480Mbps signaling rate port
 - Serial
 - 2nd External Antenna
- 9. RJ45 network connector
- 10. External WLAN antenna opening²
- 11. Power connector
- 12. Retractable Padlock loop

HP Pro SFF 400 G9 Desktop PC

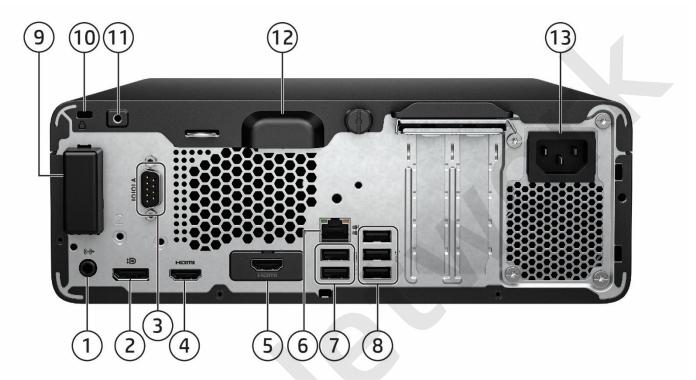


- 1. Slim optical drive (optional)
- 2. (1) Type-C[®] SuperSpeed USB 10Gbps signaling rate port
- 3. (1) Type-A SuperSpeed USB 10Gbps signaling rate port
- 4. (2) Type-A SuperSpeed USB 10Gbps signaling rate port
- 5. SD card 4.0 reader (optional)
- 6. Combo Audio Jack with CTIA and OMTP and headset support
- 7. Dual-state power button
- 8. Hard drive activity light

Not shown

- (1) PCI Express x16
- (1) PCI Express x1
- (2) M.2 (1 as M.2 2230 socket for WLAN/BT¹ and 1 as M.2 2280 socket for storage)
- 1. Must be configured at time of purchase.

HP Pro SFF 400 G9 Desktop PC



- 1. Audio line-in/line-out connector
- 2. Dual-Mode DisplayPort™ 1.4a (DP++)
- 3. Serial Port (Optional)
- 4. HDMI 1.4b
- 5. Flex Port, choice of:
 - DisplayPort™1.4a
 VGA
 - HDMI 2.1
- Serial
- Dual Type-A SuperSpeed USB 5Gbps signaling rate
- Type-C® SuperSpeed USB 10Gbps signaling rate with DisplayPort™ Alt mode
- 6. RJ45 network connector

- 7. (2) Type-A Hi-Speed USB 480Mbps signaling rate port (Supporting wake from S4/S5 with keyboard/mouse connected and enabled in BIOS)
- 8. (3) Type-A SuperSpeed USB 5Gbps signaling rate port
- 9. Internal WLAN antenna cover (optional)
- 10. Standard cable lock slot
- 11. HP Business PC Security Lock slot
- 12. Integrated accessory cable lock
- 13. Power cord connector

Not shown

Port

Optional PS/2 (2 ports) & serial port card¹ (connected with mainboard via flyer cable)

Optional parallel port1

Optional 4 Serial Port PCIe Card¹ (1 to 4 serial port dongle)

1. Each of the legacy options will occupy one rear slot.

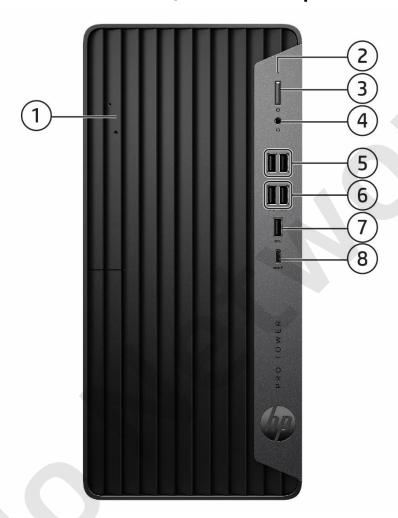
Bay

- (1) 9.5mm internal optical drive bay
- (1) 3.5" internal storage drive bay

QuickSpecs

Overview

HP Pro Tower 400/480 G9 PCI Desktop PC



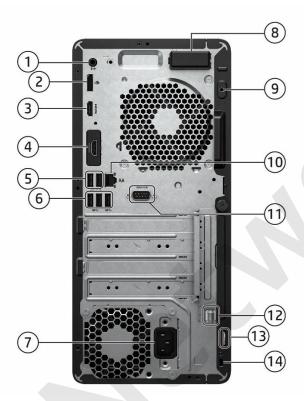
- 1. Slim optical drive (optional)
- 2. Hard drive activity light
- 3. Dual-state power button
- 4. Combo Audio Jack with CTIA and OMTP headset support
- 5. Front FlexIO Dual USB module (Option)
- 6. (2) Type-A SuperSpeed USB 10Gbps signaling rate port
- 7. (1) Type-A SuperSpeed USB 10Gbps signaling rate port
- 8. (1) Type-C[®] SuperSpeed USB 10Gbps signaling rate port

Not shown

- (1) PCI Express x16
- (1) PCI Express x1
- (1) PCI x1
- (2) M.2 (1 as M.2 2230 socket for WLAN/BT/storage¹ and 1 as M.2 2280 socket for storage)
- (1) Front Flex Port Dual SuperSpeed USB Type-A 5Gbps signaling rate²
- 1. Optional
- 2. SD card and front flex port can only select one at the same time



HP Pro Tower 400/480 G9 PCI Desktop PC



- 1. Audio line-in/line-out connector
- 2. Dual-Mode DisplayPort™ 1.4a (DP++)
- 3. HDMI 1.4b
- 4. Flex Port, choice of:
 - DisplayPort™1.4a
 VGA
 - HDMI 2.1 Serial
 - Dual Type-A SuperSpeed USB 5Gbps signaling rate
 - Type-C[®] SuperSpeed USB 10Gbps signaling rate with DisplayPort™ Alt mode)
- 5. (2) Type-A Hi-Speed USB 480Mbps signaling rate (Supporting wake from S4/S5 with keyboard/mouse connected and enabled in BIOS)

Not shown

Port

Optional PS/2 (2 ports) & serial port card (connected with mainboard via flyer cable) 1

Optional parallel port1

Optional 4 Serial Port PCIe Card¹ (1 to 4 serial port dongle)

1. Each of the legacy options will occupy one rear slot

- 6. (3) Type-A SuperSpeed USB 5Gbps signaling rate port
- 7. Power cord connector
- 8. Internal WLAN antenna cover (optional)
- 9. HP Business PC Security Lock slot
- 10. RJ45 network connector
- 11. Serial port (optional)
- 12. Integrated keyboard/mouse wire hoop
- 13. Pad lock
- 14. Standard cable lock slot

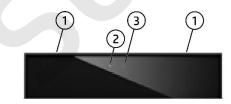
Bay

- (1) 9.5mm internal optical drive bay
- (2) 3.5" internal storage drive bay

HP ProOne 440 23.8 inch G9 All-in-One Desktop PC (Touch/Non-Touch)



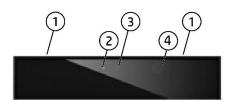
- 1. Pull-up webcam (optional)
- 2. Combo Audio Jack with CTIA and OMTP headset support
- 3. Speakers (optional)
- 4. SD media card reader (optional)
- 5. On-screen display (OSD) buttons
 - 5MP webcam with Temporal Noise Reduction (optional)



- 1. Dual microphones
- 2. Webcam light
- 3. 5MP webcam

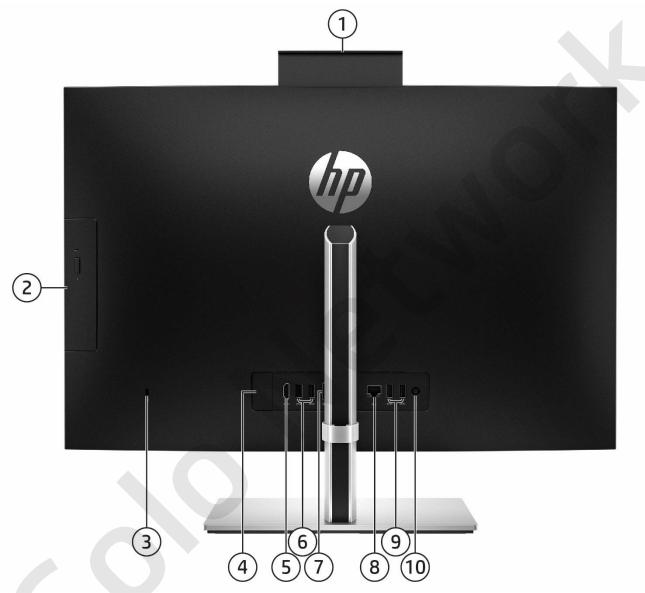
- 6. Power button
- 7. Power activity light
- 8. Type-C[®] SuperSpeed USB 10Gbps signaling rate port (charge support up to 5V/3A)
- 9. Type-A SuperSpeed USB 10Gbps signaling rate port (charge support up to 5V/1.5A)

5MP webcam with Temporal Noise Reduction + IR Sensor + Color Light Sensor (optional)



- 1. Dual microphones
- 2. Webcam light
- 3. IR/5MP/CLS webcam
- 4. IR light

HP ProOne 440 23.8 inch G9 All-in-One Desktop PC (Touch & Non-Touch)



- 1. Pull-up webcam (optional)
- 2. Optical disc drive (optional)
- 3. Standard cable lock slot
- 4. Flex Port, choice of:
 - DisplayPort™
- Serial Port
- HDMI 2.0a
- Type-C
- 5. HDMI-in
- 1. Availability may vary by country

- 6. (2) Type-A SuperSpeed USB 5Gbps signaling rate port (Supporting wake in from S4/S5 with keyboard/mouse connected and enabled BIOS)
- 7. Dual-Mode DisplayPort™ 1.4 (DP++)
- 8. RJ45 network connector
- 9. (2) Type-A SuperSpeed USB 10Gbps signaling rate port
- 10 Power connector

Overview

AT A GLANCE

- Choice of four form factors: Tower, Small Form Factor, Mini Desktop and All-in-One.
- HP developed and engineered UEFI V2.7 BIOS supporting security, manageability and software image stability.
- Latest commercial class Intel® Q670 chipsets supporting latest Intel® 12th and 13th Generation Core™ processors, featuring integrated Intel® UHD Graphics.
 - Intel® Standard Manageability (ISM) comes standard for Intel® Core® and Pentium® configurations.
 - Optional Intel® vPro® Technology upgrade with selected Core™ i5 and Core™ i7 processors (vPro® is optional and requires factory configuration).
- Processors support up to 65W for TWR/SFF/AiO and up to 35W for Mini Desktop.
- Choice of Windows 11 Professional, Windows 11 Home, and FreeDOS.
- Integrated 10/100/1000 Ethernet Controller, with optional Wi-Fi 6E, Wi-Fi 6 (802.11ax) and Wi-Fi 5 (802.11ac) and Bluetooth®.
- Up to 64GB of DDR4 Synchronous Dynamic Random Access Memory (SDRAM).
- Support for up to three video outputs via three standard video connectors and an optional third video port connector which provides the following choices: DisplayPort™, HDMI, VGA, or USB Type-C® with DisplayPort™ Output on TWR/SFF/Mini.
- Power consumption of Desktop Mini PC varies per configuration, for the best user experience, please connect PC power cord while using USB-C® cable via Super Speed USB Type-C® port in the rear side of the platform.
- Reduce clutter on Mini Desktop with single cable connection for power and video through USB Type-C[®] enabled displays with the optional USB- Type-C[®] port w/ DisplayPort Alt Mode and power intake via USB Type-C[®] Power Delivery up to 100W; reduce desktop footprint with the DM mounted behind a USB-C[™] enabled display.
- All-in-One Display can be used as a secondary display with HDMI-in.
- HDMI-in on All-in-One features Monitor Mode which disassociates panel from CPU.
- Optional Serial port available on all form factors.
- Multiple HDD data drives set up in a SATA RAID array for TWR/SFF and support RAID 1 configured from factory for TWR.
- M.2 raid array available on AiO.
- Integrated accessory cable lock helps secure cabled mouse and keyboard on TWR/SFF.
- Trusted Platform Module (TPM) 2.0.
- HP BIOSphere Gen6.
- HP Client Security Manager Gen6.
- HP Sure Click.
- HP Manageability Integration Kit Gen4.
- HP Image Assistant Gen5.
- HP Support Assistant.
- HP Tamper lock.
- High efficiency energy saving power supply.
- ENERGY STAR® certified. EPEAT® registered where applicable.
- HP Eye Ease low blue light panels (All-in-One)
- TUV certified for low blue light (All-in-One)
- TUV Ultra Low Noise certification (Mini/SFF/TWR/AIO)
- Low halogen.
- All form factors undergo MIL-STD H tests.¹
- Dust filter available for TWR/SFF/Mini Desktop.
- Protected by HP Services, including limited warranty up to 1-1-1 (terms and conditions vary by country; certain restrictions and exclusions apply); Care Packs available with up to 5 years Next Business Day Onsite Hardware Support.
- Compliance with CE (Class B) / FCC (Class B) / UL / UL62368-1) / CSA (/ CSA C22.2 No. 62368-1) / ICES-003 / CCC / VCCI (Class B) / KCC (Class B).

1. MIL-STD H testing is not intended to demonstrate fitness for U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.



NOTE: See important legal disclosures for all listed specs in their respective features sections.



Standard Features and Configurable Components (availability may vary by country)

PRODUCT NAME

HP Pro Mini 400 G9 Desktop PC HP Pro SFF 400 G9 Desktop PC HP Pro Tower 400 G9 PCI Desktop PC HP Pro Tower 480 G9 PCI Desktop PC HP ProOne 440 23.8 inch G9 All-in-One Desktop PC

OPERATING SYSTEM

Preinstalled Windows 11 Pro¹

Windows 11 Pro Education¹

Windows 11 Home - HP recommends Windows 11 Pro for business1

Windows 11 Home Single Language - HP recommends Windows 11 Pro for business1

Windows 11 Pro (preinstalled with Windows 10 Pro Downgrade)^{1,2}

Windows 11 Pro (Windows 11 Enterprise or Windows 10 Enterprise available with a Volume

Licensing Agreement)1

FreeDOS

- 1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees apply and additional requirements may apply over time for updates. See http://www.windows.com.
- 2. This system is preinstalled with Windows 10 Pro software and also comes with a license for Windows 11 Pro software and provision for recovery software. You may only use one version of the Windows software at a time. Switching between versions will require you to uninstall one version and install the other version. You must back up all data (files, photos, etc.) before uninstalling and installing operating systems to avoid loss of your data.

CHIPSET

	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
Intel® Q670	Х	X	Х	X



PROCESSORS

Intel® 12 th Generation Core™ Processors	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
Intel® Core™ i7-12700 Processor¹ 65W 2.1 GHz base frequency Up to 4.9 GHz max. turbo frequency with Intel® Turbo Boost Technology² 25 MB cache, 12 cores, 20 threads Intel® UHD Graphics 770 Supports DDR4 memory up to 3200 MT/s data rate Supports Intel® vPro® Technology and Intel® Stable Image Platform Program (SIPP)³		X	X	X
Intel® Core™ i7-12700T Processor¹ 35W 1.4 GHz base frequency Up to 4.7 GHz max. turbo frequency with Intel® Turbo Boost Technology 3.0² 25 MB cache, 12 cores, 20 threads Intel® UHD Graphics 770 Supports DDR4 memory up to 3200 MT/s data rate Supports Intel® vPro® Technology and Intel® Stable Image Platform Program (SIPP)³	x			x
Intel® Core™ i5-12600 Processor¹ 65W 3.3 GHz base frequency Up to 4.8 GHz max. turbo frequency with Intel® Turbo Boost Technology² 18 MB cache, 6 cores, 12 threads Intel® UHD Graphics 770 Supports DDR4 memory up to 3200 MT/s data rate Supports Intel® vPro® Technology and Intel® Stable Image Platform Program (SIPP)³		х	x	X
Intel® Core™ i5-12600T Processor¹ 35W 2.1 GHz base frequency Up to 4.6 GHz max. turbo frequency with Single P-core turbo Technology 18 MB cache, 6 cores, 12 threads Intel® UHD Graphics 770 Supports DDR4 memory up to 3200 MT/s data rate Supports Intel® vPro® Technology and Intel® Stable Image Platform Program (SIPP)³	x			x



QuickSpecs

HP Pro Series 400 G9 Desktops PCs

	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
Intel® Core™ i5-12500 Processor¹ 65W 3.0 GHz base frequency Up to 4.6 GHz max. turbo frequency with Intel® Turbo Boost Technology² 18 MB cache, 6 cores, 12 threads Intel® UHD Graphics 770 Supports DDR4 memory up to 3200 MT/s data rate Supports Intel® vPro® Technology and Intel® Stable Image Platform Program (SIPP)³		X	X	X
Intel® Core™ i5-12500T Processor¹ 35W 2.0 GHz base frequency Up to 4.4 GHz max. turbo frequency with Single P-core Turbo Technology18 MB cache, 6 cores, 12 threads Intel® UHD Graphics 770 Supports DDR4 memory up to 3200 MT/s data rate Supports Intel® vPro® Technology and Intel® Stable Image Platform Program (SIPP)³	X			X
Intel® Core™ i5-12400 Processor¹ 65W 2.5 GHz base frequency Up to 4.4 GHz max. turbo frequency with Intel® Turbo Boost Technology² 18 MB cache, 6 cores, 12 threads Intel® UHD Graphics 730 Supports DDR4 memory up to 3200 MT/s data rate		X	X	X
Intel® Core™ i5-12400T Processor¹ 35W 1.8 GHz base frequency Up to 4.2 GHz max. turbo frequency with Single P-core Turbo Technology 18 MB cache, 6 cores, 12 threads Intel® UHD Graphics 730 Supports DDR4 memory up to 3200 MT/s data rate	x			X



	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
Intel® Core™ i3-12300 Processor¹ 60W 3.5 GHz base frequency Up to 4.4 GHz max. turbo frequency with Single P-Core technology 12 MB cache, 4 cores, 8 threads Intel® UHD Graphics 730 Supports DDR4 memory up to 3200 MT/s data rate		X	X	X
Intel® Core™ i3-12300T Processor¹ 35W 2.3 GHz base frequency Up to 4.2 GHz max. turbo frequency with Single P-Core technology 12 MB cache, 4 cores, 8 threads Intel® UHD Graphics 730 Supports DDR4 memory up to 3200 MT/s data rate	X			X
Intel® Core™ i3-12100 Processor¹ 60W 3.3 GHz base frequency Up to 4.3 GHz max. turbo frequency with Intel® Turbo Boost Technology² 12 MB cache, 4 cores, 8 threads Intel® UHD Graphics 730 Supports DDR4 memory up to 3200 MT/s data rate		x	x	x
Intel® Core™ i3-12100T Processor¹ 35W 2.2 GHz base frequency Up to 4.1 GHz max. turbo frequency with Single P-core Technology12 MB cache, 4 cores, 8 threads Intel® UHD Graphics 730 Supports DDR4 memory up to 3200 MT/s data rate	x			x



Intel® Pentium® Processors (For FY22 Mini 400, need to add Pentium/ Celeron 35W CPU)	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
Intel® Pentium® Gold G-7400 Processor¹ 46W 3.7 GHz base frequency 6 MB cache, 2 cores, 4 threads Intel® UHD Graphics 710 Supports DDR4 memory up to 3200 MT/s data rate		x	X	x
Intel® Pentium® Gold G-7400T Processor¹ 35W 3.1 GHz base frequency 6 MB cache, 2 cores, 4 threads Intel® UHD Graphics 710 Supports DDR4 memory up to 3200 MT/s data rate	x			x
Intel® Celeron® 6900 Processor¹ 46W 3.4 GHz base frequency 4 MB cache, 2 cores, 2 threads Intel® UHD Graphics 710 Supports DDR4 memory up to 3200 MT/s data rate		X	X	X
Intel® Celeron® 6900T Processor¹ 35W 2.8 GHz base frequency 4 MB cache, 2 cores, 2 threads ntel® UHD Graphics 710 Supports DDR4 memory up to 3200 MT/s data rate	x			х



uickSpecs

HP Pro Series 400 G9 Desktops PCs

Intel® 13 th Generation Core™ Processors	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
Intel® Core™ i7-13700 processor with Intel® UHD Graphics 770 (P-core Max turbo frequency up to 5.1 GHz, up to 5.2 GHz with Intel® Turbo Boost Technology¹, 30 MB L3 cache, 16 cores) 65W² Supports Intel® vPro® Technology³		x	X	x
Intel® Core™ i7-13700T Processor with Intel® UHD Graphics 770 (P-core Max turbo frequency up to 4.8 GHz, up to 4.9 GHz with Intel® Turbo Boost Technology¹,30MB cache, 16 cores) 35W². Supports Intel® vPro® Technology³	х			х
Intel® Core™ i5-13600T processor with Intel® UHD Graphics 770 (P-core Max turbo frequency up to 4.8 GHz, 24 MB cache, 14 cores) 35W. Supports Intel® vPro® Technology	х			
Intel® Core™ i5-13500 processor with Intel® UHD Graphics 770 (P-core Max turbo frequency up to 4.8 GHz, 24 MB cache, 14 cores) 65W ^{2.} Supports Intel® vPro® Technology³		X	x	х
Intel® Core™ i5-13500T processor with Intel® UHD Graphics 770 (P-core Max turbo frequency up to 4.6 GHz, 20 MB cache, 14 cores) 35W ^{2.} Supports Intel® vPro® Technology³	x			х
		1		
Intel® Core™ i5-13400 processor with Intel® UHD Graphics 730 (P-core Max turbo frequency up to 4.6 GHz, 20 MB cache, 10 cores) 65W ^{2.}	,			х
Intel® Core™ i3-13100 processor with Intel® UHD Graphics 730 (P-core Max turbo frequency up to 4.5 GHz, 12 MB cache, 4 cores) 65W ^{2.}		x	х	х
Intel® Core™ i3-13100T processor with Intel® UHD Graphics 730 (P-core Max turbo frequency up to 4.2 GHz, , 12 MB cache, 4 cores) 35W ^{2.}	Х			х
Multi-core is designed to improve performance of certain software probenefit from use of this technology. Performance and clock frequency with the problem of the problem of the problem of the problem.	ll vary dependin	g on application wo	orkload and your h	

software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.



^{2.} Intel® Turbo Boost technology requires a PC with a processor with Intel® Turbo Boost capability. Intel® Turbo Boost performance varies depending on hardware, software and overall system configuration. See www.intel.com/technology/turboboost for more information.

^{3.} For full Intel® vPro® functionality, Windows, a vPro® supported processor, vPro® enabled chipset, vPro® enabled WLAN card and discrete TPM 2.0 are required. See https://www.intel.com/content/www/us/en/architecture-and-technology/vpro/vpro-platform-general.html.

GRAPHICS

Integrated Graphics	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
Intel® UHD Graphics 770 (integrated on 12 th & 13 th gen Core i7, Core i5- 1x500 and Core i5-1x500T)	X	Х	X	X
Intel® UHD Graphics 730 (integrated on 12 th & 13 th gen Core i3/i5-1x400, i5-1x400T)	х	х	x	X
Intel® UHD Graphics 710 (integrated on Pentium® Gold and Celeron®)	Х	X	X	X

otional Discrete Graphics Solutions	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
NVIDIA® GeForce® RTX 3050 8GB GDDR6 Graphics card			х	
NVIDIA® T400 2GB 3 mDP Graphics Card ¹		X	X	
NVIDIA® T400 4GB Graphics Card		X	Х	
Intel® Arc A380 6GB GDDR6 Graphics card			X	
AMD Radeon™ 6300M with 2 GB GDDR6 Graphics				Х
AMD Radeon™ RX 6300 2GB GDDR6 Graphics card		X	X	

^{1.} Only available with the 12th Generation processors.

Adapters and Cables	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
HP DisplayPort™ Cable	х	Х	X	X
HP DisplayPort™ to DVI-D Adapter	X	Х	X	X
HP DisplayPort™ to HDMI True 4K Adapter	X	Х	X	X
HP DisplayPort™ to VGA Adapter	Х	Х	X	Х
HP USB to Serial Port Adapter	Х	Х	X	Х

STORAGE

NOTE: Starting from November 1st, 2023, all shipments will require Windows to be installed when selecting a SSD. HDD can only be configured as additional data drives and not as the boot drive.

3.5 inch SATA Hard Disk Drives (HDD)	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
500GB* 7200RPM SATA HDD		X	Х	
1TB* 7200RPM SATA HDD		Х	Х	
2TB* 7200RPM SATA HDD		Х	Х	

2.5 inch SATA Hard Disk Drives (HDD)	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
500GB* 7200RPM SATA HDD	X			X
1TB* 7200RPM SATA HDD	X			X
1TB* 5400RPM SATA HDD	X			X
2TB* 5400RPM SATA HDD	X			X
500GB 7200RPM Self Encrypted OPAL2 SATA HDD**	X			X



QuickSpecs

HP Pro Series 400 G9 Desktops PCs

Standard Features and Configurable Components (availability may vary by country)

M.2 PCIe NMVe Solid State Drives (SSD)	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
256GB M.2 2280 PCIe NVMe SSD	X	X	X	X
512GB M.2 2280 PCIe NVMe SSD	X	X	Х	X
1TB M.2 2280 PCIe NVMe SSD	X	X	X	X
256GB M.2 2280 PCIe NVMe Three Layer Cell SSD ¹	X	X	X	X
512GB M.2 2280 PCIe NVMe Three Layer Cell SSD	X	X	Х	X
1TB M.2 2280 PCIe NVMe Three Layer Cell SSD	X	X	X	X
2TB M.2 2280 PCIe NVMe Three Layer Cell SSD	X	X	Х	Х
256GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD ¹	X	X	Х	X
512GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD	X	X	Х	X
256GB M.2 2280 PCIe OPAL2 NVMe SSD	X	X	Х	X

NOTE*: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows) of system disk is reserved for the system recovery software.

NOTE**: Storage DriveLock does not work with Self Encrypting or Optane based storage.

1. Only available with the 12th Generation processors.

Optical Disc Drives	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
HP 9.5mm Slim DVD-ROM Drive ¹		Х	X	X
HP 9.5mm Slim DVD Writer Drive		X	X	X
HP 9.5mm Slim Blu-Ray Writer Drive		X	X	X

^{1.} HD-DVD disks cannot be played on this drive. No support for DVD-RAM. Actual speeds may vary. Don't copy copyright-protected materials. Double Layer discs can store more data than single layer discs. Discs burned with this drive may not be compatible with many existing single-layer DVD drives and players.

Media Card Reader	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
SD 4.0 with 5-in-1 Interface (Supports SD, SDXC, SDHC, UHS-I, UHS-II)		X	X	
SD 3.0 with 4-in-1 Interface (Supports SD, SDXC, SDHC, UHS-I)				X



QuickSpecs

HP Pro Series 400 G9 Desktops PCs

Standard Features and Configurable Components (availability may vary by country)

MEMORY

	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
DDR4-3200 (Transfer rates up to 3200 MT/s), Max 64 GB, 2 SO-DIMM	X			X
DDR4-3200 (Transfer rates up to 3200 MT/s), Max 64 GB, 2 U-DIMM		Х	X	

Memory Configuration	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
4GB (4GB x 1)	Х	X	Х	X
8GB (4GB x 2)	Х	Х	Х	X
8GB (8GB x 1)	Х	Х	Х	X
16GB (8GB x 2)	Х	X	Х	X
16GB (16GB x 1)	X	X	Х	X
32GB (16GB x 2)	Х	X	Х	X
32GB (32GB x 1)	X	X	Х	X
64GB (32GB x 2)	X	Х	Х	Х

NOTE: For systems configured with more than 3GB of memory and a 32-bit operating system, all memory may not be available due to system resource requirements. Addressing memory above 4GB requires a 64-bit operating system.

NOTE: Memory modules support data transfer rates up to 3200 MT/s respectively depending on memory module used; actual data rate is determined by the system's configured processor. See processor specifications for supported memory data rate.

NOTE: All memory slots are customer accessible / upgradeable.

NOTE: Memory speed 3200 MT/s can be achieved via two UDIMMs per channel (2DPC) when populated with the same part number.



NETWORKING/COMMUNICATIONS

Ethernet (RJ-45) <u>Mir</u>		<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
Intel® I219-LM 1 Gigabit Network Connection LOM (vPro®)	Х	X	Х	X
Intel® Ethernet I225-T1 GbE NIC (optional)	Х			
Wireless				
Intel® Wi-Fi 6E¹ AX211 + Bluetooth® 5.3 wireless card (802.11AX 2x2 vPro®, supporting gigabit data rate²)³	Х	Х	х	X
Intel® Wi-Fi 6E¹ AX211 + Bluetooth® 5.3 wireless card (802.11AX 2x2 non-vPro®, supporting gigabit data rate²)³				X
Realtek Wi-Fi 6 ² RTL8852BE 802.11ax 2x2 with Bluetooth® 5.3 wireless card	X X		х	X
Realtek RTL8821CE 802.11ac4 1x1 with Bluetooth® 4.2 wireless card	X	X	Х	X

^{1.} Wi-Fi 6E requires a Wi-Fi 6E router, sold separately, to function in the 6GHz band. Availability of public wireless access points limited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available in countries where Wi-Fi 6E is supported. Wi-Fi 6E is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels.

NOTE: Usage of the 6GHz band relies on Windows 11 Operating System support.

KEYBOARDS AND POINTING DEVICES

Keyboards	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
HP Business Slim PS/2 Wired Keyboard		X	Х	
HP Wired Desktop 320K Keyboard	Х	Х	Х	Х
HP USB Business Slim Wired SmartCard CCID Keyboard	Х	X	X	X
HP 125 Wired Keyboard	Х	X	X	X
HP 125 Antimicrobial Wired Keyboard (China Only)	Х	Х	X	X

Keyboard & Mouse Combo

HP 655 Wireless Keyboard and Mouse Combo	X	X	X	X	
--	---	---	---	---	--

Mouse

HP PS/2 Mouse		X	X	
HP Wired Desktop 320M Mouse	Х	Х	Х	Х
HP 125 Wired Mouse	X	X	X	X
HP 125 Wired Antimicrobial Mouse (China Only)	X	X	X	X
HP 128 Wired Laser Mouse	Х	Х	Х	X



^{2.} Wi-Fi 6 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels.

^{3. 400} G9 TWR/SFF do not support Wi-Fi 6E. HP desktops that support Wi-Fi 6E require a Wi-Fi 6E router, sold separately to function in the 6GHz band. Availability of public wireless access points limited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available in countries where Wi-Fi 6E is supported. HP desktops that do not support Wi-Fi 6E do not operate under 6GHz band. The products are compatible with 6GHz and other routers, sold separately, which have capability to operate in 2.4GHz and 5GHz, in compliance with Wi-Fi 6 and prior 802.11 specs. The actual throughput depends network condition and router configuration. Internet service required and public wireless access points are limited. 4. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 5 (802.11 ac) is backwards compatible with prior 802.11 specs.

NOTE: Availability may vary by country



Standard Features and Configurable Components (availability may vary by country)

SECURITY

	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
TPM 2.0 (FW: 15.21) endpoint security controller (Infineon SLB9672/Nuvoton NPCT760HABYX) shipped with Windows 10/11 Common Criteria EAL4+ Certified. FIPS 140-2 Level 2 Certified.		X	x	х
Intrusion Sensor (Optional)		X	X	
Intrusion Sensor (integrated in the system board, can be enabled/disabled through BIOS)	х			Х
Support for chassis cable lock devices	X (10 mm barrel or smaller)	x	х	х
Support for chassis padlocks devices	X	X	X	
Support for table lock				X
SATA port disablement (via BIOS)	X	X	X	
Serial, USB enable/disable (via BIOS)	X	X	X	Х
Intel® Identify Protection Technology (IPT) ¹	X	X	X	X
Removable media write/boot control		X	X	X
Power-on password (via BIOS)	Х	X	X	X
Setup password (via BIOS)	X	X	X	Х

^{1.} Models configured with Intel® Core™ processors have the ability to utilize advanced security protection for online transactions. IPT, used in conjunction with participating web sites, provides double identity authentication by adding a hardware component in addition to the usual user name and password. IPT is initialized through an HP Client Security module

PORTS

nternal Slots and Ports	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
M.2 PCIe	(1) M.2 PCIe x1 2230 (for WLAN/BT) (1) M.2 PCIe x4 2280 (for storage)	2230 (for	(1) M.2 PCle x1 2230 (for WLAN/BT/storage ¹) (1) M.2 PCle x4 2280 (for storage)	(1) M.2 PCIe x1 2230 (for WLAN) (1) M.2 PCIe x4 2280 (for storage) (1) M.2 PCIe x3 2280 (for storage)
PCI Express v4.0 x1		1	1	
PCI Express v4.0 x16		1	1	
PCI x1			1	
SATA port		2	3	
Integrated SATA storage connector	1			

^{1.} Optional.

NOTE: For Desktop Mini with M.2 Storage config, there will be no SATA drive bracket. If you plan to use or upgrade the storage with any 2.5" SATA drive, please select a DM SATA Drive Bracket (available as both factory configured and after market option). **NOTE**: PCI slots for TWR are full height and SFF are low profile.



QuickSpecs

HP Pro Series 400 G9 Desktops PCs

Bays	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u> AiO</u>
9.5mm Slim Optical Disc Drive (ODD)		1	1	11
SD Card Reader ¹ (optional)		1	1	1
2.5" Internal Storage Drive	1			1
3.5" Internal Storage Drive		1	2	

- 1. Must be configured at time of purchase
- 2. Need to be configured at the time of purchase, either SATA or the ODD can only be selected one at the same time.

andard User Accessible Ports	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
Type-A Hi-Speed USB 480Mbps signaling rate port		2 (rear)	2 (rear)	
Type-A SuperSpeed USB 5Gbps signaling rate port	2 (rear)	3 (rear)	3 (rear)	2 (rear)
Type-A SuperSpeed USB 10Gbps signaling rate port	2 (front) 1 (rear)	3 (front)	3 (front)	2 (rear) 1 (side)
Type-C [®] SuperSpeed USB 10Gbps signaling rate port		1 (front)	1 (front)	1 (side)
Type-C [®] SuperSpeed USB 20Gbps signaling rate port	1 (front)			
Video	2 DisplayPort™ 1.4a (rear) 1 HDMI 2.1a (rear)	1 DisplayPort™ 1.4a (rear) 1 HDMI 1.4b (rear)	1 DisplayPort™ 1.4a (rear) 1 HDMI 1.4b (rear)	1 DisplayPort™1.4a 1 HDMI-in (Rear) 1.4b
Audio	1 Combo Audio Jack with CTIA and headset support (front)	1 Combo Audio Jack with CTIA & OMTP and headset support (front) 1 Audio-Line- in/Line out (rear)	OMTP and headset	1 Combo Audio Jack with CTIA and OMTP headset support (side)
Network Interface	1 RJ45 (rear)	1 RJ45 (rear)	1 RJ45 (rear)	1 RJ45 (rear)

^{1.} Upgradeable to SuperSpeed USB 10Gbps signaling rate port if configured with additional digital video port via Flex Port 1 and/or Intel® vPro®



QuickSpecs

HP Pro Series 400 G9 Desktops PCs

1

Standard Features and Configurable Components (availability may vary by country)

Rear Configurable Non-PCIe/PCI Slot User Accessible Ports Flexible Port 1, choice of one Mini **SFF TWR** Ai0 of the following: Type-A USB 2 Type-A SuperSpeed 2 Type-A SuperSpeed USB **USB 5Gbps signaling** 5Gbps signaling rate port rate port (rear) Type-C® USB 1 SuperSpeed USB 1 SuperSpeed USB 1 SuperSpeed USB 10Gbps 1 SuperSpeed USB 10Gbps signaling rate 10Gbps signaling rate signaling rate port w/ 10Gbps signaling rate port w/ DisplayPort™ port w/ DisplayPort™ DisplayPort™ Alt Mode port w/ DisplayPort™ Alt Mode Alt Mode Alt Mode and power intake via USB Type-C® Power Delivery up to 100W 1 DisplayPort™ 1.4a or 1 DisplayPort™ 1.4a or 1 DisplayPort™ 1.4a or 1 DisplayPort™ 1.4a Video HDMI 2.1a or VGA HDMI 2.1a or VGA HDMI 2.1a or VGA HDMI 2.1a or USB-C

1. Sold separately or as an optional feature

Serial (RS-232)

(1) Flexible Port 2, choice of one of the following:	· Wilni		TWR	<u>AiO</u>
Type-A USB	2 Hi-Speed USB 480Mbps signaling rate port ¹		1 Type-A SuperSpeed USB 5Gbps signaling rate port² (front)	
Serial (RS-232)	1 ¹			
2 nd External antenna	11			

1

1

1¹



^{1.} Must be configured at time of purchase

^{2.} Front flex IO – Dual USB port and SD card reader can only select one at the same time.

Standard Features and Configurable Components (availability may vary by country)

USB SPECIFICATION AND MARKETING NAME MAPPING TABLE

Marketing Name	Technical Terminology
Hi-Speed USB 480Mbps signaling rate	USB 2.0
SuperSpeed USB 5Gbps signaling rate	USB 3.2 Gen 1
SuperSpeed USB 10Gbps signaling rate	USB 3.2 Gen 2
SuperSpeed USB 20Gbps signaling rate	USB 3.2 Gen 2x2



SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS

Software

HP Easy Clean¹

HP PC Hardware Diagnostics UEFI

HP Desktop Support Utilities

HP Privacy Settings

HP Setup Integrated 00BE

HP Support Assistant²

myHP with Multicamera support (AIO&Mini)3

HP Notifications

HP Connection Optimizer

HP Smart Support⁴

HP Services Scan⁵

Microsoft Office sold separately and requires Internet access for activation

Manageability Features

HP Connect⁶

HP Image Assistant Gen5 (download)

HP Manageability Integration Kit (download)⁷

HP Client Management Script Library (download)

HP Patch Assistant (download)8

HP Driver Packs (download)

HP Cloud Recovery9

HP Client Catalog (download)

Security Management

HP Wolf Security for Business¹⁰ includes:

HP Sure Click¹¹

HP Sure Sense¹²

HP Sure Start¹³

HP Tamper Lock

HP Sure Admin¹⁴

BIOS

HP BIOSphere Gen615

HP Secure Erase¹⁶

HP DriveLock & Automatic DriveLock

BIOS Update via Network

Absolute Persistence Module¹⁷

TPM 2.0 Embedded Security Chip (Common Criteria EAL4+ Certified) (FIPS 140-2 Level 2 Certified)

- 1. HP Easy Clean requires Windows 10 RS3 and will disable the keyboard, touchscreen, and clickpad only. Ports are not disabled. See user guide for cleaning instructions.
- 2. HP Support Assistant requires Windows and Internet Access
- 3. MyHP with Multicamera support for Mini Desktop PC will only available on 13th processor and beyond.
- 4. HP Smart Support requires HP TechPulse to be installed. For more information about how to enable or to download HP Smart Support, please visit: http://www.hp.com/smart-support.
- 5. HP Services Scan is provided with Windows Update on select products and will check entitlement on each hardware device to determine if an HP TechPulse-enabled service has been purchased, and will download applicable software automatically. HP TechPulse is a telemetry and analytics platform that provides critical data around devices and applications and is not sold as a standalone service. HP TechPulse follows stringent GDPR privacy regulations and is ISO27001, ISO27701, ISO277017 and SOC2 Type2 certified for Information Security. Internet access with connection to TechPulse portal is required. For full system requirements or to disable this feature, please visit http://www.hpdaas.com/requirements. Not applicable in China.
- 6. HP Connect for Microsoft Endpoint Manager is available from the Azure Market Place for HP Pro, Elite, Z and Point-of-Sale PCs managed with Microsoft Endpoint Manager. Subscription to Microsoft Endpoint Manager required and sold separately. Network connection required.



QuickSpecs

HP Pro Series 400 G9 Desktops PCs

- 7. HP Manageability Integration Kit can be downloaded from http://www.hp.com/go/clientmanagement.
- 8. HP Patch Assistant available on select HP PCs with the HP Manageability Kit that are managed through Microsoft System Center Configuration Manager. HP Manageability Integration Kit can be downloaded from http://www8.hp.com/us/en/ads/clientmanagement/overview.html.
- 9. HP Cloud Recovery is available for Z by HP, HP Elite and Pro desktops and laptops PCs with Intel® or AMD processors and requires an open, wired network connection. Note: You must back up important files, data, photos, videos, etc. before use to avoid loss of data. Detail, please refer to: https://support.hp.com/us-en/document/c05115630.
- 10. HP Wolf Security for Business requires Windows 10 or higher, includes various HP security features and is available on HP Pro, Elite, RPOS and Workstation products. See product details for included security features and OS requirement.
- 11. HP Sure Click requires Windows 10 Pro or higher or Enterprise. See https://bit.ly/2PrLT6A_SureClick for complete details.
- 12. HP Sure Sense is available on select HP PCs with Windows 10 Pro, Windows 10 Enterprise, Windows 11 Pro, or Windows 11 Enterprise OS.
- 13. HP Sure Start Gen7 is available on select HP PCs and requires Windows 10 and higher
- 14. HP Sure Admin requires Windows 10 or higher, HP BIOS, HP Manageability Integration Kit from http://www.hp.com/go/clientmanagement and HP Sure Admin Local Access Authenticator smartphone app from the Android or Apple store.
- 15. HP BIOSphere Gen6 features may vary depending on the platform and configuration.
- 16. HP Secure Erase for the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane™.
- 17. Absolute firmware module is shipped turned off and can only be activated with the purchase a license subscription and full activation of the software agent. License subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. Certain conditions apply. For full details visit: http://www.absolute.com/about/legal/agreements/absolute



Standard Features and Configurable Components (availability may vary by country)

UNIT ENVIRONMENT AND OPERATING CONDITIONS

General Unit Operating Guidelines

- Keep the computer away from excessive moisture, direct moisture and the extremes of heat and cold, to ensure that unit is operated within the specified operating range.
- Leave a 10.2 cm (4 in) clearance on all vented sides of the computer to permit the required airflow.
- Never restrict airflow into the computer by blocking any vents or air intakes.
- Do not stack computers on top of each other or place computers so near each other that they are subject to each other's re-circulated or preheated air.
- Occasionally clean the air vents on the front, back, and any other vented side of the computer. Lint, dust and other foreign matter can block the vents and limit the airflow.
- If the computer is to be operated within a separate enclosure, intake and exhaust ventilation must be provided on the enclosure, and the same operating quidelines listed above will still apply.

Temperature Range Operating: 5° to 35° C¹

Non-Operating for AiO: -20° to 60° C1

Non-Operating for MT/SFF/DM: -30° to 60° C1

Relative Humidity Operating: 10% to 90% (non-condensing at ambient)

Non-operating: 5% to 95% (non-condensing at ambient)

Maximum Altitude Operating: 5000m

(unpressurized) Non-operating: 50000ft (15240 m)

1. Operating temperature is de-rated 1.0 deg C per 300 m (1000 ft) to 3000 m (10,000 ft) above sea level, no direct sustained sunlight. Maximum rate of change is 10 deg C/Hr. The upper limit may be limited by the type and number of options installed.



This product has received or is in the process of being certified to the following approvals and may be

Standard Features and Configurable Components (availability may vary by country)

ENVIRONMENTAL & INDUSTRY

HP Pro Mini 400 G9 Desktop PC

Eco-Label Certifications

& declarations	Inis product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: • IT ECO declaration • US ENERGY STAR® • US Federal Energy Management Program (FEMP) • EPEAT® Climate+ registered in the United States. See http://www.epeat.net for registration status in your country. • TCO Certified • China Energy Conservation Program (CECP) • China State Environmental Protection Administration (SEPA) • Taiwan Green Mark • Korea Eco-label • Japan PC Green label • Commission Regulation (EC) No 617/2013 (ErP Lot 3)			
System Configuration	The configuration used for the End Desktop model is based on a Typio			Emissions data for the
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, !	50Hz	100VAC, 60Hz
Normal Operation (Short idle)	7.23 W	7.31 V	V	7.07 W
Normal Operation (Long idle)	2.16 W	2.24 W		2.01 W
Sleep	2.14 W	2.21 V	V	1.99 W
Off	0.62 W	0.7 W		0.47 W
	NOTE: Energy efficiency data listed is HP computers marked with the ENERG Protection Agency (EPA) ENERGY STAR STAR® certified configurations, then e disk drive, a high efficiency power sup	SY STAR® Logo are cert R® specifications for co nergy efficiency data li ply, and a Microsoft Wi	ified with the applic mputers. If a mode sted is for a typical ndows® operating	able U.S. Environmental family does not offer ENERGY ly configured PC featuring a hard system.
Heat Dissipation*	115VAC, 60Hz	230VAC, !	50Hz	100VAC, 50Hz
Normal Operation (Short idle)	24.7 BTU/hr	25 BTU/hr		24.2 BTU/hr
Normal Operation (Long idle)	7.4 BTU/hr	7.7 BTU/hr		6.9 BTU/hr
Sleep	7.3 BTU/hr	7.6 BTU/hr		6.8 BTU/hr
Off	2.1 BTU/hr	2.41 BTL	J/hr	1.6 BTU/hr
	NOTE: Heat dissipation is calculated b hour.	ased on the measured	watts, assuming th	e service level is attained for one
Declared Noise				
Emissions	Sound Power			ound Pressure
(in accordance with ISO 7779 and ISO 9296)	(L _{WAd} , bels)		(L	_{-pAm} , decibels)
Typically Configured – Idle	2.9			17



	2.0	10
	3.0	19
features and • 2 SODIMM r • Interchange	or components contained in the production of the	ct may include:
production.		
_		ive 2006/66/EC
Mercury grea	ter than 1ppm by weight	
• This product 2011/65/EC. • This HP pro Directive — 20 • This product and Toxic Ent • Plastics par • This product 10% ITE-deri • This product	t is in compliance with the Restrictions duct is designed to comply with the Was 202/96/EC. It is in compliance with California Propostorcement Act of 1986). Its weighing over 25 grams used in the part contains a minimum of 35% post-consequence post-consumer recycled plastic.* It is 95.1% recycle-able when properly of the properly o	ste Electrical and Electronic Equipment (WEEE) sition 65 (State of California; Safe Drinking Water product are marked per ISO11469 and ISO1043. sumer recycled (PCR) plastic (by wt.); including disposed of at end of life.
		562g
Internal:		79g
the HP Gener http://www.f Asbestos Certain Azo Certain Azo Certain Brod Cadmium Chlorinated Formaldehy Halogenate Lead carbod Lead and Le Mercuric Ox Nickel – finiticarried by the Ozone Depl Polybromin	does not contain any of the following stal Specification for the Environment at approximately period and specification for the Environment at approximately period and set of the Environment at approximately period and set of the Environment at approximately period and set of the Environment at a set of the En	ubstances in excess of regulatory limits (refer to inment/pdf/gse.pdf): e used as flame retardants in plastics
	features and 2 SODIMM r Interchange Spare parts a production. This battery(Batteries use Mercury great Cadmium cand Toxic Enterproduct Cand Toxic Enterproduct Cand Toxic Enterproduct Cadmium cand Cadmiu	This battery(s) in this product comply with EU Direct Batteries used in the product do not contain: Mercury greater than 1ppm by weight Cadmium greater than 20ppm by weight Battery size: CR2032 (coin cell) Battery type: Lithium • This product is in compliance with the Restrictions 2011/65/EC. • This HP product is designed to comply with the War Directive – 2002/96/EC. • This product is in compliance with California Proporand Toxic Enforcement Act of 1986). • Plastics parts weighing over 25 grams used in the proporation of the product contains a minimum of 35% post-contains are recycled plastic.* • This product contains a minimum of 35% post-contains are recycled plastic.* • This product is 95.1% recycle-able when properly of the Polyce plastic content percentage is based on the definition of the External: PAPER/Paper Internal: PAPER/Molded Pulp PLASTIC/Polyethylene low density - Letter product does not contain any of the following state HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/envirous Asbestos • Certain Azo Colorants • Certain Brominated Flame Retardants – may not be



	• Polyvinyl Chloride (PVC) — except for wires and cables, and certain retail packaging has been
	voluntarily removed from most applications.
	Radioactive Substances
	Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging:
	• Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
	• Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
	Design packaging materials for ease of disassembly.
	Maximize the use of post-consumer recycled content materials in packaging materials.
	Use readily recyclable packaging materials such as paper and corrugated materials.
	Reduce size and weight of packages to improve transportation fuel efficiency.
	• Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To
and Recycling	recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.
	The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment. Global Citizenship Report
	http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html
	Eco-label certifications
	http://www8.hp.com/us/en/hp-information/environment/ecolabels.html
	ISO 14001 certificates:
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K_
	Certificate.pdf
	and
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf



HP Pro SFF 400 G9 Desktop PC

Eco-Label	Certifications
& declarat	ions

This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- IT ECO declaration
- US ENERGY STAR®
- US Federal Energy Management Program (FEMP)
- EPEA® Climate+ registered in the United States. See http://www.epeat.net for registration status in your country.
- TCO Certified
- China Energy Conservation Program (CECP)
- China State Environmental Protection Administration (SEPA)
- Taiwan Green Mark
- Korea Eco-label
- Japan PC Green label
- Commission Regulation (EC) No 617/2013 (ErP Lot 3)

System	Configur	ation
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The configuration used for the Energy Consumption and Declared Noise Emissions data for the Desktop model is based on a Typically Configured Desktop.

Desktop model is based on a Typically Configured Desktop.				
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz	
Normal Operation (Short idle)	12.1240 W	12.1460 W	12.0990 W	
Normal Operation (Long idle)	10.3820 W	10.4110 W	10.3460 W	
Sleep	0.9410 W	0.9380 W	0.9420 W	
Off	0.7770 W	0.7750 W	0.7750 W	

NOTE: Energy efficiency data listed is for an ENERGY STAR® certified product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are certified with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® certified configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.

Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz
Normal Operation (Short idle)	41.3428 W	41.4179 W	41.2576 W
Normal Operation (Long idle)	35.4026 W	35.5015 W	35.2799 W
Sleep	3.2088 W	3.1986 W	3.2122 W
Off	2.6496 W	2.6428 W	2.6428 W

NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (L _{WAd} , bels)	Sound Pressure (L _{pAm} , decibels)
Typically Configured – Idle	3.2	21

Fixed Disk – Random		2.7	22
writes		3.2	23
Optical Drive sequential		4.6	36.9
reads			
Longevity and Upgrading	features and, • 2 DIMM mer	or components contained in the production	
	production.		eriod and or for up to "5" years after the end of
Batteries	This battery(s) in this product comply with EU Direct	ive 2006/66/EC
	Mercury grea Cadmium gre Battery size:	d in the product do not contain: ter than 1ppm by weight ater than 20ppm by weight CR2032 (coin cell)	
	Battery type:		
Additional Information	2011/65/EC. This HP pro Directive – 20 This product and Toxic Enf Plastics par This product 10% ITE-deri	duct is designed to comply with the Wa 002/96/EC. t is in compliance with California Propo orcement Act of 1986). ts weighing over 25 grams used in the p	of Hazardous Substances (RoHS) directive - ste Electrical and Electronic Equipment (WEEE) sition 65 (State of California; Safe Drinking Water product are marked per ISO11469 and ISO1043. sumer recycled (PCR) plastic (by wt.); including
			nition set in the IEEE 1680.1-2018 standard.
Packaging Materials	External:	PAPER/Corrugated	1019g
(vary by country)	Internal:	PAPER/Molded pulp	434g
(tany by boarday,		PLASTIC/Polyethylene low density	29q
Material Usage	the HP Gener http://www.f • Asbestos • Certain Azo • Certain Brou • Cadmium • Chlorinated • Formaldehy • Halogenate • Lead carbor • Lead and Le • Mercuric Ox • Nickel – fini carried by the	does not contain any of the following stal Specification for the Environment at ap.com/hpinfo/globalcitizenship/environments Colorants minated Flame Retardants — may not be hydrocarbons Paraffins I de d Diphenyl Methanes I nates and sulfates I ad compounds I de Batteries I shes must not be used on the external stales.	ubstances in excess of regulatory limits (refer to onment/pdf/gse.pdf):



	Polychlorinated Biphenyl (PCB)
	Polychlorinated Terphenyls (PCT) Polychiad (NVC) P
	• Polyvinyl Chloride (PVC) — except for wires and cables, and certain retail packaging has been
	voluntarily removed from most applications. • Radioactive Substances
	Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging:
l ackaging osage	
	• Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
	• Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
	Design packaging materials for ease of disassembly.
	Maximize the use of post-consumer recycled content materials in packaging materials.
	Use readily recyclable packaging materials such as paper and corrugated materials.
	Reduce size and weight of packages to improve transportation fuel efficiency.
	Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To
and Recycling	recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP
	sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible
	manner.
	The FILMERS directive (2002/05/FC) requires manufacturers to provide treatment information for
	The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly
	instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These
	instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM
	customers who integrate and re-sell HP equipment.
HP Inc. Corporate	For more information about HP's commitment to the environment:
Environmental	
Information	Global Citizenship Report
	http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html
	Eco-label certifications
	http://www8.hp.com/us/en/hp-information/environment/ecolabels.html
	ISO 14001 certificates:
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K_
	Certificate.pdf
	and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf
	nttp://www.np.com/npmno/globalcitizensinp/environment/pui/cert.pui



HP Pro Tower 400/480 G9 PCI Desktop PC

Eco-Label Certifications This product has received or is in the process of being certified to the following approvals and may be & declarations labeled with one or more of these marks: IT ECO declaration **US ENERGY STAR®** US Federal Energy Management Program (FEMP) EPEAT® Climate+ registered in the United States. See http://www.epeat.net for registration status in your country. TCO Certified China Energy Conservation Program (CECP) China State Environmental Protection Administration (SEPA) Taiwan Green Mark Korea Eco-label Japan PC Green label Commission Regulation (EC) No 617/2013 (ErP Lot 3) **System Configuration** The configuration used for the Energy Consumption and Declared Noise Emissions data for the Desktop model is based on a Typically Configured Desktop. **Energy Consumption** (in accordance with US 230VAC, 50Hz 115VAC, 60Hz 100VAC, 60Hz **ENERGY STAR® test** method) Normal Operation 12.6930 W 12.6980 W 12.6900 W (Short idle) Normal Operation 10.9580 W 10.9770 W 10.9590 W (Long idle) Sleep 0.9940 W 0.9940 W 0.9890 W Off 0.8030 W 0.8020 W 0.7990 W **NOTE:** Energy efficiency data listed is for an ENERGY STAR® certified product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are certified with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® certified configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system. **Heat Dissipation*** 115VAC, 60Hz 230VAC, 50Hz 100VAC, 60Hz Normal Operation 43.2831 W 43.3002 W 43.2729 W (Short idle) Normal Operation 37.3668 W 37.4316 W 37.3702 W (Long idle) Sleep 3.3895 W 3.3895 W 3.3725 W Off 2.7382 W 2.7348 W 2.7246 W **NOTE:** Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour. **Declared Noise**



Idle

writes

Emissions

(in accordance with

Fixed Disk – Random

ISO 7779 and ISO 9296) Typically Configured -

Sound Power

(Lwad, bels)

3.0

3.4

Sound Pressure

(L_{pAm}, decibels)

20

23

Optical Drive - Sequential reads		4.9		38
Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include: • 2 DIMM memory slots • Interchangeable M.2 PCIe NVME SSD & 2.5"/3.5" SATA HDD			
	Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.			
Batteries	This battery(s) in this product comply with EU Directive 2006/66/EC			
	Batteries used in the product do not contain: Mercury greater than 1ppm by weight Cadmium greater than 20ppm by weight			
	Battery size: CR2032 (coin cell) Battery type: Lithium			
Additional Information	• • • •			
Packaging Materials	External:	PAPER/Corrugated		1110 g
(vary by country)		PAPER/Molded Pulp		654 g
	Internal:	PLASTIC/Polyethylene low density - L		32 g
Material Usage	This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf): • Asbestos • Certain Azo Colorants • Certain Brominated Flame Retardants – may not be used as flame retardants in plastics • Cadmium • Chlorinated Hydrocarbons • Chlorinated Paraffins • Formaldehyde • Halogenated Diphenyl Methanes • Lead carbonates and sulfates • Lead and Lead compounds • Mercuric Oxide Batteries • Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. • Ozone Depleting Substances • Polybrominated Biphenyls (PBBs) • Polybrominated Biphenyl Ethers (PBBEs) • Polybrominated Biphenyl Oxides (PBBOs) • Polychlorinated Biphenyl (PCB) • Polychlorinated Terphenyls (PCT)			



Standard Features and Configurable Components (availability may vary by country)

	 Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
	Radioactive Substances
	Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging:
	• Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
	• Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
	Design packaging materials for ease of disassembly.
	• Maximize the use of post-consumer recycled content materials in packaging materials.
	 Use readily recyclable packaging materials such as paper and corrugated materials.
	 Reduce size and weight of packages to improve transportation fuel efficiency.
	 Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management and Recycling	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.
	The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.
HP Inc. Corporate	For more information about HP's commitment to the environment:
Environmental	
Information	Global Citizenship Report
	http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html
	Eco-label certifications
	http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates:
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K_
	Certificate.pdf
	and
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf



Standard Features and Configurable Components (availability may vary by country)

HP ProOne 440 23.8 inch G9 All-in-One Desktop PC

Eco-Label Certifications & declarations

This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- IT ECO declaration
- US ENERGY STAR®
- US Federal Energy Management Program (FEMP)
- EPEAT® Climate+ registered in the United States. See http://www.epeat.net for registration status in your country.
- TCO Certified
- China Energy Conservation Program (CECP)
- China State Environmental Protection Administration (SEPA)
- Taiwan Green Mark
- Korea Eco-label
- Japan PC Green label
- Commission Regulation (EC) No 617/2013 (ErP Lot 3)

System Configuration

The configuration used for the Energy Consumption and Declared Noise Emissions data for the

Desktop model is based on a "Typically Configured Desktop".

	Desktop model is based on a Typically Configured Desktop .		
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz
Normal Operation (Short idle)	16.4700 W	16.1300 W	16.2800 W
Normal Operation (Long idle)	1.7600 W	1.7500 W	1.7300 W
Sleep	1.7400 W	1.7500 W	1.7300 W
Off	0.6200 W	0.6700 W	0.6200 W

NOTE: Energy efficiency data listed is for an ENERGY STAR® certified product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are certified with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® certified configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.

Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz
Normal Operation (Short idle)	49.6 BTU/hr	49.6 BTU/hr	49.5 BTU/hr
Normal Operation (Long idle)	5.2 BTU/hr	5.2 BTU/hr	5.2 BTU/hr
Sleep	5.2 BTU/hr	5.2 BTU/hr	5.2 BTU/hr
Off	3 BTU/hr	3 BTU/hr	3 BTU/hr

NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (L _{WAd} , bels)	Sound Pressure (L _{pAm} , decibels)
Typically Configured – Idle	2.8	15
Fixed Disk – Random writes	2.8	17



Standard Features and Configurable Components (availability may vary by country)

Optical Drive – Sequential reads		4.7	36.0	
Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include: • 2 SODIMM memory slots Spare parts are available throughout the warranty period and or for up to "5" years after the end of			
Batteries	production. This battery(s) in this product comply with EU Directive 2006/66/EC			
batteries	Batteries used in the product do not contain: Mercury greater than 1ppm by weight Cadmium greater than 20ppm by weight			
	Battery size: Battery type:	CR2032 (coin cell)		
Additional Information	• This product 2011/65/EC. • This HP pro Directive – 20 • This product and Toxic Ent • Plastics par • This product 10% ITE-deri	 This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC. This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043. This product contains a minimum of 50% post-consumer recycled (PCR) plastic (by wt.); including 10% ITE-derived post-consumer recycled plastic.* This product is 95.1% recycle-able when properly disposed of at end of life. 		
Packaging Materials	External:	PAPER/Corrugated	1605 g	
(vary by country)	Internal:	PLASTIC/Polyethylene Expanded - E		
(vary by country)	internat.	PLASTIC/Polyethylene low density -		
Material Usage	This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf): - Asbestos - Certain Azo Colorants - Certain Brominated Flame Retardants – may not be used as flame retardants in plastics - Cadmium - Chlorinated Hydrocarbons - Chlorinated Paraffins - Formaldehyde - Halogenated Diphenyl Methanes - Lead carbonates and sulfates - Lead and Lead compounds - Mercuric Oxide Batteries - Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user Ozone Depleting Substances - Polybrominated Biphenyls (PBBs) - Polybrominated Biphenyl Ethers (PBBEs) - Polybrominated Biphenyl Oxides (PBBOs) - Polychlorinated Biphenyl (PCB) - Polychlorinated Terphenyls (PCT)			



Standard Features and Configurable Components (availability may vary by country)

	 Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. Radioactive Substances Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging: • Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. • Eliminate the use of ozone-depleting substances (ODS) in packaging materials. • Design packaging materials for ease of disassembly. • Maximize the use of post-consumer recycled content materials in packaging materials. • Use readily recyclable packaging materials such as paper and corrugated materials. • Reduce size and weight of packages to improve transportation fuel efficiency. • Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management and Recycling	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner. The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment. Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates: http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K_Certificate.pdf and



QuickSpecs

HP Pro Series 400 G9 Desktops PCs

Standard Features and Configurable Components (availability may vary by country)

SERVICE AND SUPPORT

On-site Warranty¹: One-year (1-1-1) limited warranty delivers one year of on-site, next business day² service for parts and labor support. Service offers terms up to 5 years by choosing an optional HP Care Pack. To choose the right level of service for your HP product, visit HP Care Pack Central: http://www.hp.com/qo/cpc.³

- 1. Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.
- 2. On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.
- 3. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.



Technical Specifications - Processors

PROCESSORS

12th and 13th Generation Intel® 12th Generation Core™ Processors¹

All HP ProDesk & ProOne 400 Business PC models featuring this technology include processors that are part of the Intel® Stable Image Platform Program (SIPP) designed to ensure the stability promise inherent in the value proposition of the HP ProDesk and ProOne 400 Business PC.

Intel® Advanced Management Technology (AMT)¹ v16 – An advanced set of remote management features and functionality which provides network administrators the latest and most effective tools to remotely discover, heal, and protect networked client systems regardless of the system's health or power state. AMT 16 includes the following advanced management functions:

- Support for configuration of Intel® AMT 16.0 capabilities
- No reset after provisioning
- Support for Intel® Enterprise Digital Fence
- The Platform Discovery Utility can now discover these additional Intel® products:
 - Intel® Identity Protection Technology with One Time Password
 - Public Key Infrastructure
 - Multi Factor Authentication
- Profile Editor and Profile Editor Plugin Interface
- Required Permissions for Solutions Framework

1. Intel® Active Management Technology requires an Intel® AMT-enabled chipset, network hardware and software, as well as connection with a power source and a corporate network connection. Setup requires configuration by the purchaser and may require scripting with the management console or further integration into existing security frameworks to enable certain functionality. It may also require modifications of implementation of new business processes.



QuickSpecs

Technical Specifications - Display Panel Specifications

DISPLAY PANEL SPECIFICATIONS

NOTE: All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

HP ProOne 440 23.8 inch G9 All-in-One Desktop PC

23.8" diagonal IPS widescreen WLED backlit anti-glare LCD (1920 x 1080)

Projected Capacitive Touch supports up to 10 touch-points

Support HW low blue light feature

 Type
 IPS WLED Backlit LCD

 Active area (mm)
 527.04 x 296.46

 Native Resolution (HxV)
 1920 x 1080

Refresh Rate 60 Hz @ 1920 x 1080

Aspect ratio 16:9

Pixel pitch (HxV)(mm) 0.2745 x 0.2745

Contrast ratio 1000:1

Brightness* 300nits*

Viewing angle (HxV) 178° x 178°

Backlight lamp life (to half brightness) 30,000 hours minimum

Color support Up to 16.7 million colors with 8 Bit(6 Bit + FRC)

Color gamutsRGB 99%Anti-glareYesResponse Time14ms

Default color temperature Warm (6500K)

23.8" diagonal IPS widescreen WLED backlit anti-glare LCD (1920 x 1080) non-touch

Support HW low blue light feature

Type IPS WLED Backlit LCD
Active area (mm) 527.04 x 296.46
Native Resolution (HxV) 1920 x 1080

Refresh Rate 60 Hz @ 1920 x 1080

Aspect ratio 16:9

Pixel pitch (HxV)(mm) 0.2745 x 0.2745

Contrast ratio 1000:1
Brightness* 250nits*
Viewing angle (HxV) 178° x 178°

Backlight lamp life (to half brightness) 30,000 hours minimum

Color support Up to 16.7 million colors with 8 Bit(6 Bit + FRC)

Color gamutNTSC 72%Anti-glareYesResponse Time14ms

Default color temperature Warm (6500K)

^{*}Actual brightness will be lower with touchscreen

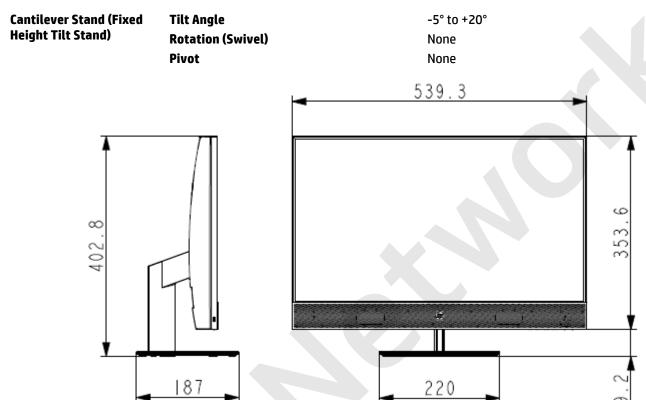


^{*}Actual brightness will be lower with touchscreen

Technical Specifications - All-in-One Stand Specifications

ALL-IN-ONE STAND SPECIFICATIONS

HP ProOne 440 23.8 inch G9 All-in-One Desktop PC





Technical Specifications - All-in-One Stand Specifications



Height Adjustment (Landscape Mode)

Height Adjustment (Portrait Mode)

Tilt Angle **Rotation (Swivel)**

Pivot

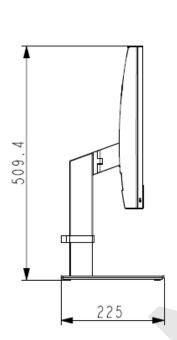
5.12 in / 130mm

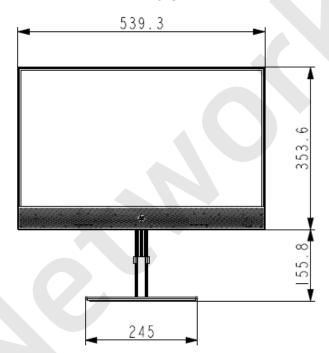
N/A

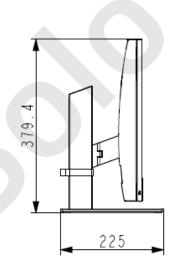
-5° to +20°

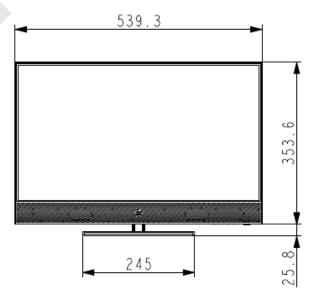
±45°

None



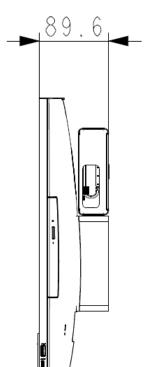


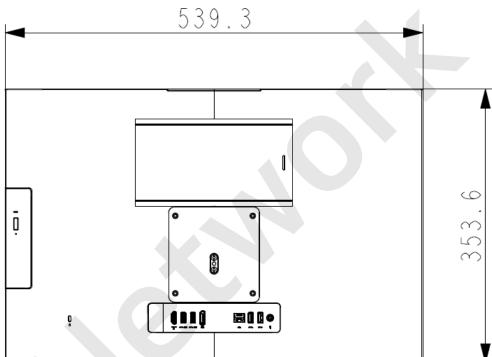




Technical Specifications - All-in-One Stand Specifications

No Stand Tilt Angle None (VESA COVER with EPS Holder) **Rotation (Swivel)** None **Pivot** None





Technical Specifications – Graphics

GRAPHICS

HP Pro Mini 400 G9 Desktop PC

Intel® UHD Graphics (integrated)

Graphics Controller Integrated

DisplayPort™ Multimode capable; supports HDCP, Display Port Audio , HBR2 link rates and Multi-Stream

Technology for a maximum of 3 displays connected to any output controlled by Intel®

Graphics

HDMI (on board/optional) Supports HDMI 2.1 features

Supports HDCP 2.3

Supports audio over HDMI

VGA (optional) VGA output

USB-C® DP Alt Mode(optional) DisplayPort™ over the USB-C® module

Memory The actual amount of maximum graphics memory can be >4GB. System memory is allocated

for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide

an optimal balance between graphics and system memory use.

Maximum Color Depth up to 16 bits/color

Graphics/Video API Support HEVC 10b Enc/12b Dec HW

VP9 12b Dec HW

HDR Rec. 2020 DX12

 Max. Resolution (HDMI)
 4096 x 2160@60Hz

 Max. Resolution (DP)
 4096 x 2304@60Hz

 Max Resolution (optional VGA)
 2048 x 1536@60Hz

 Max Resolution (optional DP)
 5120 x 2160@60Hz

 Max Resolution (optional HDMI)
 3840 x 2160@60Hz



Technical Specifications – Graphics

HP Pro SFF 400 G9 Desktop PC Intel® HD Graphics (integrated)

VGA Controller Integrated

DisplayPort™ Multimode capable; supports HDCP, Display Port Audio, Onboard support HBR2 link

rates/option DP support to HBR3 and Multi-Stream Technology for a maximum of 3 displays

connected to any output controlled by Intel® Graphics

HDMI (onboard / optional) Supports HDMI 2.1 features (onboard HDMI support HDMI 1.4; Option HDMI support HDMI 2.1)

Supports HDCP 2.3 (Support HDCP 1.4/2.3)

Supports audio over HDMI

VGA (optional) VGA output

USB-C® DP Alt Mode (optional) DisplayPort™ over the optional USB-C® module (Support DP1.4 HBR2)

Memory The actual amount of maximum graphics memory can be >4GB. System memory is allocated

for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide

an optimal balance between graphics and system memory use.

Maximum Color Depth up to 16 bits/color

Graphics/Video API Support HEVC 10b Enc/12b Dec HW

VP9 12b Dec HW à AV1 decode support 8/10b, 4:2:0

HDR Rec. 2020 DX12

 Max. Resolution (VGA Option)
 2048 x 1536@60Hz

 Max. Resolution (Onboard HDMI)
 1920 x 1080@60Hz

 Max. Resolution (Option HDMI)
 3840 x 2160@60Hz

Max. Resolution (On board DP)HBR2: 4096 x 2304@60hz 24 bppMax. Resolution (Option DP)HBR3: 5120 x3200 @60hz 24 bppMax. Resolution (Option Type C)DP HBR2: 4096 x2304 @60hz 24bpp

NVIDIA® Quadro T400 2GB Graphics Card

 Engine Clock
 2100 MHz

 Memory Clock
 5001 MHz

 Memory Size (width)
 2GB (64-bit)

 Memory Type
 256M x 16 GDDR6

 Max. Resolution (DP)
 7680x4320@120Hz

Multi Display Support 4 displays HDCP Compliance Yes Rear I/O connectors (bracket) mDPx3

Cooling (active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption (W) 30W

PCB form-factor with bracket LP PCB with LP bracket



Technical Specifications – Graphics

NVIDIA® T400 4GB Graphics Card

Engine Clock2100 MHzMemory Clock5001 MHzMemory Size (width)4GB (64-bit)Memory Type512M x 16 GDDR6

Max. Resolution (DP) 7680x4320@120Hz

Multi Display Support4 displaysHDCP ComplianceYesRear I/O connectors (bracket)mDPx3

Cooling (active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption (W) 30W

PCB form-factor with bracket LP PCB with LP bracket

AMD Radeon™ RX 6300 2GB GDDR6 Graphics card

Engine Clock Base: 1512 Mhz Boost: 2040 Mhz

Memory Size / Width 2GB / 32bit

Graphic Memory Type / Clock 512Mx32 GDDR6 ,1 pcs / 16Gbps

 Max. Resolution (HDMI)
 7680x4320@60Hz

 Max. Resolution (DP)
 7680x4320@120Hz

Multi Display Support 2 displays

HDCP Compliance Yes

Rear I/O connectors (bracket) HDMIx1+ DPx1 (LP)

Cooling (active/passive) Active
Total power consumption (W) 32W

Form-factor X:160.2mm/Y:68.9mm/Z: 22.6mm PCB with single slot



Technical Specifications – Graphics

HP Pro Tower 400 G9 Desktop PC

Intel® HD Graphics (integrated)

VGA Controller Integrated

DisplayPort™ Multimode capable; supports HDCP, Display Port Audio, Onboard support HBR2 link

rates/option DP support to HBR3 and Multi-Stream Technology for a maximum of 3 displays

connected to any output controlled by Intel® Graphics

HDMI (onboard / optional) Supports HDMI 2.1 features (onboard HDMI support HDMI 1.4; Option HDMI support HDMI 2.1)

Supports HDCP 2.3 (Support HDCP 1.4/2.3)

Supports audio over HDMI

VGA (optional) VGA output

USB-C® DP Alt Mode (optional) DisplayPort™ over the optional USB-C® module (Support DP1.4 HBR2)

Memory The actual amount of maximum graphics memory can be >4GB. System memory is allocated

for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide

an optimal balance between graphics and system memory use.

Maximum Color Depth up to 16 bits/color

Graphics/Video API Support HEVC 10b Enc/12b Dec HW

VP9 12b Dec HW à AV1 decode support 8/10b, 4:2:0

HDR Rec. 2020 DX12

 Max. Resolution (VGA Option)
 2048 x 1536@60Hz

 Max. Resolution (Onboard HDMI)
 1920 x 1080@60Hz

 Max. Resolution (Option HDMI)
 3840 x 2160@60Hz

Max. Resolution (On board DP)HBR2: 4096 x 2304@60hz 24 bppMax. Resolution (Option DP)HBR3: 5120 x3200 @60hz 24 bppMax. Resolution (Option Type C)DP HBR2: 4096 x2304 @60hz 24bpp

NVIDIA® Quadro T400 2GB Graphics Card

 Engine Clock
 2100 MHz

 Memory Clock
 5001 MHz

 Memory Size (width)
 2GB (64-bit)

 Memory Type
 256M x 16 GDDR6

 Max. Resolution (DP)
 7680x4320@120Hz

Multi Display Support 4 displays
HDCP Compliance Yes
Rear I/O connectors (bracket) mDPx3

Cooling (active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption (W) 30W

PCB form-factor with bracket LP PCB with LP bracket

NVIDIA® T400 4GB Graphics Card

 Engine Clock
 2100 MHz

 Memory Clock
 5001 MHz

 Memory Size (width)
 4GB (64-bit)

 Memory Type
 512M x 16 GDDR6

 Max. Resolution (DP)
 7680x4320@120Hz

Multi Display Support4 displaysHDCP ComplianceYesRear I/O connectors (bracket)mDPx3

Cooling (active/passive) Active fan-sink (Active cooling with dynamic speed)



Technical Specifications – Graphics

Total power consumption (W) 30W

PCB form-factor with bracket LP PCB with LP bracket

NVIDIA® GeForce® RTX 3050 8GB GDDR6 Graphics Card

Engine Clock Base: 1515 Mhz Boost: 1755 Mhz

Frame Buffer Size / Width 8GB/128bit

Graphic Memory Type / Clock 512Mx32 GDDR6 @ 4 pcs/14Gbps

 Max. Resolution (HDMI)
 7680x4320@60Hz

 Max. Resolution (DP)
 7680x4320@60Hz

Multi Display Support 4 displays

HDCP Compliance Yes

Rear I/O connectors (bracket) HDMIx1+ DPx3

Cooling (active/passive) Active fansink with 4 pin fan control

Total power consumption (W) 120W

Form-factor ATX (X:144.7mm/Y:111.15mm/Z: 36.70mm) PCB with ATX dual slot bracket

NOTE: 8 pins connector requires for RTX3050 with 400W PSU

Intel® Arc™ A380 6GB GDDR6 Graphics card4

Engine Clock 2150Mhz
Frame Buffer Size / Width 6GB/96bit

Graphic Memory Type / Clock GDDR6 ,3 pcs/15.5Gbps
Max. Resolution (HDMI) 4096 x2160@60Hz
Max. Resolution (DP) 7680x4320@60Hz

Multi Display Support 4 displays

HDCP Compliance Yes

Rear I/O connectors (bracket) DP x3 + HDMI x1

Cooling (active/passive) Active
Total power consumption (W) 75W

AMD Radeon™ RX 6300 2GB GDDR6 Graphics card

Engine Clock Base: 1512 Mhz Boost: 2040 Mhz

Memory Size / Width 2GB / 32bit

Graphic Memory Type / Clock 512Mx32 GDDR6 ,1 pcs / 16Gbps

 Max. Resolution (HDMI)
 7680x4320@60Hz

 Max. Resolution (DP)
 7680x4320@120Hz

Multi Display Support 2 displays

HDCP Compliance Yes

Rear I/O connectors (bracket) HDMIx1+ DPx1 (LP)

Cooling (active/passive) Active
Total power consumption (W) 32W

Form-factor X:160.2mm/Y:68.9mm/Z: 22.6mm PCB with single slot



Technical Specifications – Storage

STORAGE

NOTE: Starting from November 1st, 2023, all shipments will require Windows to be installed when selecting a SSD. HDD can only be configured as additional data drives and not as the boot drive.

500GB 7200RPM 3.5in SATA HDD

Capacity500GBRotational Speed7,200 rpmInterfaceSATA 6.0 Gb/s

Buffer Size 32MB

 Logical Blocks
 976,773,168

 Seek Time
 11 ms (Average)

 Height
 1in/2.54cm

Width Media diameter: 3.5 in/8.89 cm

Physical size: 4 in/10.2 cm

Operating Temperature 41° to 131° F (5° to 55° C)

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

1TB 7200RPM 3.5in SATA HDD

Capacity 1TB

Rotational Speed 7,200 rpm Interface SATA 6 Gb/s **Buffer Size** 64MB

Logical Blocks 1,953,525,168
Seek Time 11 ms (Average)
Height 1in/2.54cm

Width (nominal) Media diameter: 3.5 in/8.89 cm

Physical size: 4 in/10.2 cm

Operating Temperature 41° to 131° F (5° to 55° C)

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

2TB 7200RPM 3.5in SATA HDD

Capacity 2TB

Rotational Speed 7,200 rpm Interface SATA 6 Gb/s Buffer Size 128MB

 Logical Blocks
 3,907,050,336

 Seek Time
 11 ms (Average)

 Height
 1.028in/26.11mm

Width (nominal) Media diameter: 3.5 in/8.89 cm

Physical size: 4 in/10.2 cm



Technical Specifications – Storage

Operating Temperature 41° to 131° F (5° to 55° C)

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

500GB 7200RPM 2.5in SATA HDD

Capacity 500GB **Rotational Speed** 7,200 rpm Interface SATA 6 Gb/s **Buffer Size** Up to 128MB **Logical Blocks** 976,773,168 **Seek Time** 12 ms (Average) Height 0.283in/7.2mm (Max) Width (nominal) 2.75 in/70 mm (nominal) **Operating Temperature** 41° to 131° F (5° to 55° C)

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

1TB 7200RPM 2.5in SATA HDD

Capacity 1TB

Rotational Speed 7,200 rpm Interface SATA 6 Gb/s **Buffer Size** Up to 128MB **Logical Blocks** 1,953,525,168 **Seek Time** 12 ms (Average) 0.283 in/7.2 mm (Max) Height Width (nominal) 2.75 in/70 mm (nominal) 41° to 131° F (5° to 55° C) **Operating Temperature**

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

1TB 5400RPM 2.5in SATA HDD

Operating Temperature

Capacity 1TB **Rotational Speed** 5,400 rpm Interface SATA 6 Gb/s **Buffer Size** Up to 128MB **Logical Blocks** 1,953,525,168 **Seek Time** 12ms (Average) Height 0.283in/7.2mm (Max.) Width (nominal) 2.75in/70mm (nominal)

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

41° to 131° F (5° to 55° C)



Technical Specifications – Storage

2TB 5400RPM 2.5in SATA HDD

Capacity 2TB

Rotational Speed 5,400 rpm **Interface** SATA 6 Gb/s **Buffer Size** 128MB

Logical Blocks 3,907,050,336 **Seek Time** 12 ms (Average)

Height0.374in/9.5mm (nominal)Width (nominal)2.75in/70mm (nominal)Operating Temperature41° to 131° F (5° to 55° C)

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

500GB 7200RPM 2.5in Self Encrypted OPAL2 SATA HDD

Capacity 500GB

Architecture Self-Encrypting (SED) Solid State Drive with SATA interface

Interface SATA 6 Gb/s

Buffer Size 128MB

Logical Blocks 976,773,168

Seek Time 12 ms (Average)

Height 0.283in/7.2mm (Max.)

Width 2.75in/70mm (nominal)

Operating Temperature 41° to 131° F (5° to 55° C)

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

256GB M.2 2280 PCIe NVMe SSD

Capacity 256GB Interface PCIe NVMe

Minimum Sequential Read $2000 \text{ MB/s} \pm 10\%$ Minimum Sequential Write $900 \text{ MB/s} \pm 10\%$ Logical Blocks500,118,192FeaturesTRIM; L1.2

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.



Technical Specifications – Storage

512GB M.2 2280 PCIe NVMe SSD

Capacity512GBInterfacePCIe NVMe

 $\begin{tabular}{llll} \textbf{Minimum Sequential Read} & 2200 \ MB/s \pm 10\% \\ \textbf{Minimum Sequential Write} & 1000 \ MB/s \pm 10\% \\ \textbf{Logical Blocks} & 1,000,215,216 \\ \textbf{Features} & TRIM; L1.2 \\ \end{tabular}$

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

1TB M.2 2280 PCIe NVMe SSD

Capacity 1TB

Interface PCIe NVMe

 $\begin{tabular}{llll} \textbf{Minimum Sequential Read} & 2200 \ MB/s \pm 10\% \\ \textbf{Minimum Sequential Write} & 1600 \ MB/s \pm 10\% \\ \textbf{Logical Blocks} & 2,000,409,264 \\ \textbf{Features} & TRIM; L1.2 \\ \end{tabular}$

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

256GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Capacity256GBInterfacePCIE Gen4x4Minimum Sequential Read4000 MB/s ±10%Minimum Sequential Write2000 MB/s ±10%Logical Blocks500,118,192

Features TRIM; L1.2; Pyrite 2.0

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

512GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Capacity 512GB
Interface PCIE Gen4x4
Minimum Sequential Read 6400 MB/s ±10%
Minimum Sequential Write 3500 MB/s ±10%
Logical Blocks 1,000,215,216
Features TRIM; L1.2; Pyrite 2.0

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.



Technical Specifications – Storage

1TB M.2 2280 PCIe NVMe Three Layer Cell SSD

Capacity 1TB

InterfacePCIE Gen4x4Minimum Sequential Read6400 MB/s ±10%Minimum Sequential Write5000 MB/s ±10%Logical Blocks2,000,409,264FeaturesTRIM; L1.2; Pyrite 2.0

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

2TB M.2 2280 PCIe NVMe Three Layer Cell SSD

Capacity 2TB

Interface PCIE Gen4x4

Minimum Sequential Read 6400 MB/s ±10%

Minimum Sequential Write 5000 MB/s ±10%

Logical Blocks 4,000,797,360

Features TRIM; L1.2; Pyrite 2.0

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

256GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Value SSD

Capacity256GBInterfacePCIE NVMeMinimum Sequential Read2000 MB/s ±10%Minimum Sequential Write900 MB/s ±10%Logical Blocks500,118,192

Features Pyrite 2.0; TRIM; L1.2

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

256GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD

Capacity 256GB
Interface PCIE Gen4x4
Minimum Sequential Read 4000 MB/s ±10%
Minimum Sequential Write 2000 MB/s ±10%
Logical Blocks 500,118,192

Features TRIM; L1.2; TCG Opal 2.0

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.



Technical Specifications – Storage

512GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD

512GB Capacity **Interface** PCIE Gen4x4 Minimum Sequential Read 6400 MB/s ±10% **Minimum Sequential Write** 3500 MB/s ±10% **Logical Blocks** 1,000,215,216

Features TRIM; L1.2; TCG Opal 2.0

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

HP 9.5mm Slim DVD-ROM Drive

Height 9.5 mm height

Orientation Either horizontal or vertical

Interface type SATA/ATAPI

Dimensions (W x H x D) 5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel

Weight (max) Up to 0.31 lb (140g) without bezel

Read Speeds DVD+R/-R/+RW/

> -RW/+R DL /-R DL Up to 8X DVD-ROM Up to 8X CD-ROM, CD-R Up to 24X CD-RW Up to 24X

Access time

(typical reads, including

Random: DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical) settling) Full stroke: DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical)

Source Slimline SATA DC power receptacle **Power**

> DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)

Environmental conditions

Temperature 41° to 122° F (5° to 50° C)

(operating - non-condensing) Relative Humidity 10% to 80%

Maximum Wet Bulb Temperature 84° F (29° C)



Technical Specifications – Storage

HP 9.5mm Slim DVD Writer Drive

Height 9.5 mm height

Orientation Either horizontal or vertical

Interface type SATA/ATAPI

Dimensions (W x H x D) 5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel

Weight (max) Up to 0.31 lb (140 g) Without bezel

 Write Speeds
 DVD-R DL - Up to 6X

 DVD+R - Up to 8X

DVD+RW - Up to 8X DVD+R DL - Up to 6X DVD-R - Up to 8X DVD-RW - Up to 6X CD-R - Up to 24X CD-RW - Up to 10X

Read Speeds DVD-RW, DVD+RW - Up to 8X

DVD-R DL, DVD+R DL - Up to 8X DVD+R, DVD-R - Up to 8X

DVD-ROM DL, DVD-ROM - Up to 8X

CD-ROM, CD-R - Up to 24X

CD-RW - Up to 24X

Access time Random DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical) (typical reads, including Full Stroke DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical)

(typical reads, including settling)

Full Stroke DVD-ROM: 320 ms (typical)

Stop Time 6 seconds (typical)

Power Source Slimline SATA DC power receptacle

DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)

Environmental conditions Temperature 41° to 122° F (5° to 50° C)

(operating - non-condensing) Relative Humidity 10% to 80%

Maximum Wet Bulb Temperature 84° F (29° C)

HP 9.5mm Slim Blu-Ray Writer Drive

Height 9.5 mm height

Orientation Either horizontal or vertical

Interface type SATA/ATAPI

Dimensions (W x H x D) 5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel

Weight (max) Up to 0.37 lb (170g) without bezel

Write Speeds BD-R SL/DL Up to 6X

BD-R TL/QL Up to 4X BD-RE Up to 2X DVD-R Up to 8X DVD-RW Up to 6X DVD+R Up to 8X DVD+RW Up to 8X DVD-RAM Up to 5X CD-R Up to 24X CD-RW Up to 10X

Read Speeds BD-ROM Up to 6X BD-R Up to 6X

BD-RE SL/DL Up to 6X



Technical Specifications – Storage

BD-RE TL Up to 4X DVD-ROM Up to 8X DVD-R Up to 8X DVD-RW Up to 8X DVD+R Up to 8X DVD+RW Up to 8X BDMV (AACS Compliant

Disc)

Up to 6x/2x (Read/Play) DVD-RAM Up to 5x DVD-Video (CSS Compliant Disc) Up to 8x/4x (Read/Play)

Up to 8x/4x (Read/Play) CD-R/RW/ROM Up to 24x

CD-DA (DAE) Up to 24X/10X (Read/Play)

Random BD-ROM: 205 ms (typical), DVD-ROM: 185 ms (typical),

Access time CD-ROM: 165 ms (typical)

(typical reads, including Full Stroke BD-ROM: 350 ms (typical), DVD-ROM: 345 ms (typical),

settling) CD-ROM: 340 ms (typical)

Source Slimline SATA DC power receptacle

DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p

Power DC Current 5 VDC -1200 mA typical, 2000 mA maximum

Temperature 41° to 122° F (5° to 50° C)

Environmental conditions Relative Humidity 10% to 80%

(operating - non-condensing) Maximum Wet Bulb Temperature 84° F (29° C)





NETWORKING AND COMMUNICATIONS

Intel® I219-LM 1 Gigabit	Network Connection LOM (vPro®)	
Connector	RJ-45	
System Interface	PCI (Intel® proprietary) + SMBus	
Data rates supported	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s	
IEEE Compliance	IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable) IEEE 802.3az EEE (Energy Efficient Ethernet)	
Performance	TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS) Large send offload and Giant send offload Receiving Side Scaling (Hash Mode Only) Jumbo Frame 9K	
Power consumption	Cable Disconnection: 25mW 100Mbps Full Run: 450mW 1000bp Full Run: 1000mW WoL Enable (S3/S4/S5): 50mW WoL Disable (S3/S4/S5): 25mW	
Power	ACPI compliant – multiple power modes	
Management	Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumption	
Management Interface	Auto MDI/MDIX Crossover cable detection	
IT Manageability	Wake-on-LAN from modern standby or sleep state (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only), Microsoft Windows Fast Startup must be disabled. PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30)) Comprehensive diagnostic and configuration software suite	
Security & Manageability	Virtual Cable Doctor for Ethernet cable status Intel® vPro® support with appropriate Intel® chipset components	
Security & Manageability	I inter- vero- support with appropriate inter- chipset components	



	it Network Connection LOM (non-vPro®)		
Connector	RJ-45		
System Interface	PCI (Intel® proprietary) + SMBus		
Data rates supported	1. 10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14)		
	2. 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30)		
	3. 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 802.3 clauses 40)		
	4. 2.5 Gbit/s operation (2.5GBASE-T; IEEE 802.3bz Clause 126)		
	5. Auto-Negotiation (Automatic Speed Selection)		
	Full Duplex Operation at all Speeds, Half Duplex operation at 10, 100 & 1000 Mbit/s		
IEEE Compliance	IEEE 802.1p QoS (Quality of Service) Support		
	IEEE 802.1q VLAN support		
	IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable)		
	IEEE 802.3az EEE (Energy Efficient Ethernet)		
	IEEE 802.3i 10BASE-T		
	IEEE 802.3u 100BASE-TX		
	IEEE 802.3ab 1000BAE-T		
	IEEE 802.3bz 2.5GBASE-T		
Performance	TCP/IP/UDP Checksum Offload (configurable)		
	Protocol Offload (ARP & NS)		
	Large send offload and Giant send offload		
	Receiving Side Scaling (Hash Mode Only)		
	Jumbo Frame 9K		
Power consumption	Cable Disconnection: 25mW		
	100Mbps Full Run: 450mW		
	1000bp Full Run: 1000mW		
	WoL Enable (S3/S4/S5): 50mW		
	WoL Disable (S3/S4/S5): 25mW		
Power	ACPI compliant – multiple power modes		
Management	Situation-sensitive features reduce power consumption		
	Advanced link down power saving for reducing link down power consumption		
Management Interface	Auto MDI/MDIX Crossover cable detection		
IT Manageability	Wake-on-LAN from modern standby or sleep state (Magic Packet and Microsoft Wake-Up Frame);		
-	Wake-on-LAN from off (Magic Packet only), Microsoft Windows Fast Startup must be disabled.		
	PXE 2.1 Remote Boot		
	Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30))		
	Comprehensive diagnostic and configuration software suite		
	Virtual Cable Doctor for Ethernet cable status		
Security & Manageability	Intel® non-vPro® support with appropriate Intel® chipset components		



	(1x1) Wi Fi® and Bluetooth® 4.2 wireless card¹
Wireless LAN Standards	IEEE 802.11a
	IEEE 802.11b
	IEEE 802.11g
	IEEE 802.11n
	IEEE 802.11ac
	IEEE 802.11d
	IEEE 802.11e
	IEEE 802.11h
	IEEE 802.11i
	IEEE 802.11k
	IEEE 802.11r
I	IEEE 802.11v
Interoperability	Wi-Fi® certified modules
Frequency Band	802.11b/g/n
	• 2.402 – 2.482 GHz
	802.11a/n/ac
	• 4.9 – 4.95 GHz (Japan)
	• 5.15 – 5.25 GHz
	• 5.25 – 5.35 GHz
	• 5.47 – 5.725 GHz
	• 5.825 – 5.850 GHz
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps
	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11n: max 150Mbps
	• 802.11ac: max 433.3Mbps
Modulation	Direct Sequence Spread Spectrum
	BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
	51 514, Q1 514, CC14, 10 Q111 1, 0 1 Q111 1, 250 Q111 1
Security ²	• IEEE and Wi-Fi® certified 64 / 128 bit WEP encryption for a/b/g mode only
Security	• AES-CCMP: 128 bit in hardware
	• 802.1x authentication
	WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
	• WPA2 certification
	WPA3 certification
	• IEEE 802.11i
	• WAPI
Network Architecture	Ad-hoc (Peer to Peer)
Models	
	Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power ³	• 802.11b: +14dBm minimum
	• 802.11g: +12dBm minimum
_	• 802.11a: +12dBm minimum
	• 802.11n HT20(2.4GHz): +12dBm minimum
	• 802.11n HT40(2.4GHz): +12dBm minimum
	• 802.11n HT20(5GHz): +10dBm minimum
	• 802.11n HT40(5GHz): +10dBm minimum
	• 802.11ac VHT80(5GHz): +10dBm minimum
Power Consumption	• Transmit mode 2.0 W
rower consumption	
	• Receive mode 1.6 W



	Idle mode (PSP) 180 mW (WLAN Associated)
	• Idle mode 50 mW (WLAN unassociated)
	Connected Standby 10mW
	• Radio disabled 8 mW
Power Management	ACPI and PCI Express compliant power management
	802.11 compliant power saving mode
Receiver Sensitivity ⁴	802.11b, 1Mbps: -93.5dBm maximum
	802.11b, 11Mbps: -84dBm maximum
	802.11a/g, 6Mbps: -86dBm maximum
	802.11a/g, 54Mbps: -72dBm maximum
	802.11n, MCS07: -67dBm maximum
	802.11n, MCS15: -64dBm maximum
	802.11ac, MCS0: -84dBm maximum
	802.11ac, MCS9: -59dBm maximum
Antenna type	High efficiency antenna.
	One embedded dual band 2.4/5 GHz antenna is provided to the card to support WLAN
	communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard
Dimensions	Type 2230: 2.3 x 22.0 x 30.0 mm
Weight	Type 2230: 2.8g
Operating Voltage	3.3v +/- 9%
Temperature	Operating: 14° to 158° F (–10° to 70° C)
	Non-operating: -40° to 176° F (-40° to 80° C)
Humidity	Operating: 10% to 90% (non-condensing)
	Non-operating: 5% to 95% (non-condensing)
Altitude	Operating: 0 to 10,000 ft (3,048 m)
	Non-operating: 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF;
	LED OFF – Radio ON
	etooth 4.0/4.1/4.2 wireless card Technology
Bluetooth® Specification	4.0/4.1/4.2 wireless card Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH)
	BLE: 0~39 (2 MHz/CH)
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps
	BLE: 1 Mbps data rate; throughput up to 0.2 Mbps
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels
	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or
	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5) The Bluetooth component shall operate as a Class II Bluetooth device with a maximum
	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5) The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.
	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5) The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR. Peak (Tx) 330 mW
	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5) The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR. Peak (Tx) 330 mW Peak (Rx) 230 mW
	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5) The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR. Peak (Tx) 330 mW
Transmit Power	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5) The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR. Peak (Tx) 330 mW Peak (Rx) 230 mW
	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5) The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR. Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Transmit Power Power Consumption Bluetooth® Software Supported Li Topology	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5) The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR. Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW USB 2.0 compliant
Power Consumption Bluetooth® Software Supported Li	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5) The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR. Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW USB 2.0 compliant Microsoft Windows Bluetooth Software



Power Management	ETS 300 328, ETS 300 826
Certifications	Low Voltage Directive IEC950
	UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance
	LE Link Layer Ping
	LE Dual Mode
	LE Link Layer
	LE Low Duty Cycle Directed Advertising
	LE L2CAP Connection Oriented Channels
	Train Nudging & Interlaced Scan
	BT4.2 ESR08 Compliance
	LE Secure Connection- Basic/Full
	LE Privacy 1.2 –Link Layer Privacy
	LE Privacy 1.2 –Extended Scanner Filter Policies
	LE Data Packet Length Extension
	FAX Profile (FAX)
	Basic Imaging Profile (BIP)2
	Headset Profile (HSP)
	Hands Free Profile (HFP)
	Advanced Audio Distribution Profile (A2DP)

^{1.} Wi-Fi 5 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 5 (802.11 ac) is backwards compatible with prior 802.11 specs.

- 2. Check latest software/driver release for updates on supported security features.
- 3. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
- 4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

Realtek RTL8852BE 802.11 rate) ¹	ax 2x2 Wi-Fi® + Bluetooth® 5.3 wireless card (802.11ax 2x2, supporting gigabit data
Wireless LAN Standards	IEEE 802.11a
	IEEE 802.11b
	IEEE 802.11g
	IEEE 802.11n
	IEEE 802.11ac
	IEEE 802.11ax
	IEEE 802.11d
	IEEE 802.11e
	IEEE 802.11h
	IEEE 802.11i
	IEEE 802.11k
	IEEE 802.11r
	IEEE 802.11v
Interoperability	Wi-Fi® certified modules
Frequency Band	802.11b/g/n/ax
-	• 2.402 – 2.482 GHz
	802.11a/n/ac/ax
	• 4.9 – 4.95 GHz (Japan)
	• 5.15 – 5.25 GHz



	• 5.25 – 5.35 GHz
	• 5.47 – 5.725 GHz
	• 5.825 – 5.850 GHz
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps
	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11n: max 300Mbps
	• 802.11ac: max 866.7Mbps
	• 802.11ax: max 1201Mbps
Modulation	Direct Sequence Spread Spectrum
	BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM
Security ²	• IEEE and Wi-Fi® certified 64 / 128 bit WEP encryption for a/b/g mode only
•	AES-CCMP: 128 bit in hardware
	• 802.1x authentication
	• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
	WPA2 certification
	WPA3 certification
	• IEEE 802.11i
	• WAPI
Network Architecture	Ad-hoc (Peer to Peer)
Models	
	Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power ³	• 802.11b: +18.5dBm minimum
	• 802.11g: +17.5dBm minimum
	• 802.11a: +18.5dBm minimum
	• 802.11n HT20(2.4GHz): +15.5dBm minimum
	• 802.11n HT40(2.4GHz): +14.5dBm minimum
	• 802.11n HT20(5GHz): +15.5dBm minimum
	• 802.11n HT40(5GHz): +14.5dBm minimum
	• 802.11ac VHT80(5GHz): +11.5dBm minimum
	• 802.11ax HE40(2.4GHz): +10dBm minimum
	• 802.11ax HE80(5GHz): +10dBm minimum
Power Consumption	• Transmit mode:2.5 W
Tower consumption	• Receive mode:2 W
	• Idle mode (PSP): 180 mW (WLAN Associated)
	• Idle mode:50 mW (WLAN unassociated)
	Connected Standby/Modern Standby: 10mW
	Radio disabled: 8 mW
Power Management	ACPI and PCI Express compliant power management
. Onei Finingement	802.11 compliant power saving mode
Receiver Sensitivity ⁴	802.11b, 1Mbps: -93.5dBm maximum
Receiver Sensitivity	802.11b, 11Mbps: -84dBm maximum
	802.11a/g, 6Mbps: -86dBm maximum
	802.11a/g, 54Mbps: -72dBm maximum
	802.11n, MCS07: -67dBm maximum
	802.11n, MCS15: -64dBm maximum
	802.11ac, MCS0: -84dBm maximum
	802.11ac, MCS9: -59dBm maximum
	•802.11ax, MCS11(HE40): -57dBm maximum
Antenna type	•802.11ax, MCS11(HE80): -54dBm maximum High efficiency antenna with spatial diversity, mounted in the display enclosure



<u> </u>	To a such added duel hand 2 A/F Cilla antenna a constitution of the constitution of th
	Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN
P P	MIMO communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm
	2. Type 1216: 1.67 x 12.0 x 16.0 mm
Weight	1. Type 2230: 2.8g
	2. Type 126: 1.3g
Operating Voltage	3.3v +/- 9%
Temperature	Operating: 14° to 158° F (–10° to 70° C)
11	Non-operating: -40° to 176° F (-40° to 80° C)
Humidity	Operating: 10% to 90% (non-condensing)
AlataJ.	Non-operating: 5% to 95% (non-condensing)
Altitude	Operating: 0 to 10,000 ft (3,048 m)
LED Activity	Non-operating: 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF; LED OFF – Radio ON
HP Integrated Module with Blu	etooth 4.0/4.1/4.2/5.0/5.1/5.2/5.3 wireless card Technology
Bluetooth [®] Specification	4.0/4.1/4.2/5.0/5.1/5.2 /5.3 wireless card Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH)
	BLE: 0~39 (2 MHz/CH)
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps
.	BLE: 1 Mbps data rate; throughput up to 0.2 Mbps
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels
	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or
	864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum
HallSillit Powel	transmit power of + 4 dBm for BR and EDR.
Dower Consumption	Peak (Tx): 330 mW
Power Consumption	Peak (1X): 330 IIIW
	Peak (Rx): 230 mW
	FERN (NX). 230 HIV
	Selective Suspend: 17 mW
Electrical Interface	Microsoft Windows Bluetooth Software
Bluetooth® Software Supported Link Topology	Microsoft Windows ACPI, and USB Bus Support
	ECC (47 CED) Part 1EC Section 15 247 9 15 240
Power Management	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Certifications	ETS 300 328, ETS 300 826
	Las Malta as Birantina IECOEO
	Low Voltage Directive IEC950
	III. CCA and CE Mark
	UL, CSA, and CE Mark
	Peak (Tx): 330 mW
	Peak (Rx): 230 mW
	reak (nx). 230 iliw
	Selective Suspend: 17 mW
Power Management	Microsoft Windows Bluetooth Software
rower management	וייונו טטטוג wiiiuuws Diueluulii Suitwale
Certifications	
בכו נווונמנוטווס	



Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance
	LE Link Layer Ping
	LE Dual Mode
	LE Link Layer
	LE Low Duty Cycle Directed Advertising
	LE L2CAP Connection Oriented Channels
	Train Nudging & Interlaced Scan
	BT4.2 ESR08 Compliance
	LE Secure Connection- Basic/Full
	LE Privacy 1.2 –Link Layer Privacy
	LE Privacy 1.2 –Extended Scanner Filter Policies
	LE Data Packet Length Extension
	FAX Profile (FAX)
	Basic Imaging Profile (BIP)2
	Headset Profile (HSP)
	Hands Free Profile (HFP)
	Advanced Audio Distribution Profile (A2DP)
	BT5.1
	ESR9/10 Compliance
	LE Advertisement Extensions
	Channel Selection Algo
	Limited High Duty Cycle Non-Connectable Advertising
	2Mbps LE
	LE Long Range

- 1. Wi-Fi 6 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels.
- 2. Check latest software/driver release for updates on supported security features.
- 3. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
- 4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

Intel® AX211 Wi-Fi 6E +Blue	etooth® 5.3 wireless card M.2 160MHz CNVi WW WLAN¹
Wireless LAN Standards	IEEE 802.11a
	IEEE 802.11b
	IEEE 802.11g
	IEEE 802.11n
	IEEE 802.11ac
	IEEE 802.11ax
	IEEE 802.11d
	IEEE 802.11e
	IEEE 802.11h
	IEEE 802.11i
	IEEE 802.11k
	IEEE 802.11r
	IEEE 802.11v
Interoperability	Wi-Fi® certified
Frequency Band	802.11b/g/n/ax
	• 2.402 – 2.482 GHz
	802.11a/n/ac/ax
	• 4.9 – 4.95 GHz (Japan)
	• 5.15 – 5.25 GHz
	• 5.25 – 5.35 GHz
	• 5.47 – 5.725 GHz



	• 5.825 – 5.850 GHz
	• 5.955 – 6.415 GHz
	• 6.435 – 6.515 GHz
	• 6.535 – 6.875 GHz
	• 6.895 – 7.115 GHz
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps
	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11n: max 300Mbps
	• 802.11ac: 1733Mbps
	• 802.11ax: max 2.4Gbps
Modulation	Direct Sequence Spread Spectrum
	OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
	,1024QAM
Security ²	• IEEE and Wi-Fi® compliant 64 / 128 bit WEP encryption for a/b/g mode only
	AES-CCMP: 128 bit in hardware
	• 802.1x authentication
	• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
	WPA2 certification
	WPA3 certification
	• IEEE 802.11i
	• WAPI
Network Architecture	Ad-hoc (Peer to Peer)
Models	
	Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power ³	• 802.11b: +17dBm minimum
	• 802.11g: +16dBm minimum
	• 802.11a: +17dBm minimum
	• 802.11n HT20(2.4GHz): +14dBm minimum
	• 802.11n HT40(2.4GHz): +13dBm minimum
	• 802.11n HT20(5GHz): +14dBm minimum
	• 802.11n HT40(5GHz): +13dBm minimum
	• 802.11ac VHT80(5GHz): +10dBm minimum
	• 802.11ac VHT160(5GHz): +10dBm minimum
	• 802.11ax HE40(2.4GHz): +12dBm minimum
	• 802.11ax HE80(5GHz): +10dBm minimum
	• 802.11ax HE160(5GHz): +10dBm minimum
Power Consumption	• Transmit mode 2.0 W
	Receive mode 1.6 W
	• Idle mode (PSP) 180 mW (WLAN Associated)
	Idle mode 50 mW (WLAN unassociated)
	Connected Standby 10mW
	Radio disabled 8 mW
Power Management	ACPI and PCI Express compliant power management
Power Management	802.11 compliant power saving mode
Power Management Receiver Sensitivity ⁴	
_	802.11 compliant power saving mode
_	802.11 compliant power saving mode •802.11b, 1Mbps: -93.5dBm maximum
	802.11 compliant power saving mode •802.11b, 1Mbps: -93.5dBm maximum •802.11b, 11Mbps: -84dBm maximum
_	802.11 compliant power saving mode •802.11b, 1Mbps: -93.5dBm maximum •802.11b, 11Mbps: -84dBm maximum •802.11a/g, 6Mbps: -86dBm maximum
_	802.11 compliant power saving mode •802.11b, 1Mbps: -93.5dBm maximum •802.11b, 11Mbps: -84dBm maximum •802.11a/g, 6Mbps: -86dBm maximum •802.11a/g, 54Mbps: -72dBm maximum



	• 802.11ac, MCS9(VHT80): -59dBm maximum
	• 802.11ac, MCS9(VHT160): -58.5dBm maximum
	•802.11ax, MCS11(HE40): -57dBm maximum
	•802.11ax, MCS11(HE80): -54dBm maximum
	•802.11ax, MCS11(HE160): -53.5dBm maximum
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure
	Two embedded dual band 2.4/5/6 GHz antennas are provided to the card to support WLAN
	MIMO communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm
	2. Type 1216: 1.67 x 12.0 x 16.0 mm
Weight	1. Type 2230: 2.8g
	2. Type 1216: 1.3g
Operating Voltage	3.3v +/- 9%
Temperature	Operating: 14° to 158° F (–10° to 70° C)
	Non-operating: –40° to 176° F (–40° to 80° C)
Humidity	Operating: 10% to 90% (non-condensing)
	Non-operating: 5% to 95% (non-condensing)
Altitude	Operating: 0 to 10,000 ft (3,048 m)
	Non-operating: 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF; LED OFF – Radio ON
HP Integrated Module with Blue	etooth 4.0/4.1/4.2/5.0/5.1/5.2/5.3 wireless card Technology
Bluetooth [®] Specification	4.0/4.1/4.2/5.0/5.1/5.2 5.3 wireless card Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH)
Training of Available Chainies	BLE: 0~39 (2 MHz/CH)
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps
Data Mates and I moughput	BLE: 1 Mbps data rate; throughput up to 0.2 Mbps
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels
	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or
	864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum
Transmit rower	transmit power of + 9.5 dBm for BR and EDR.
Power Consumption	Peak (Tx): 330 mW
i ower consumption	Cuk (1A). 330 HW
	Peak (Rx): 230 mW
	Con (IV) 250 IIII
	Selective Suspend: 17 mW
Bluetooth® Software Supported	Microsoft Windows Bluetooth Software
Link Topology	introsoft windows blactooth software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
	·
Power Management Certifications	ETS 300 328, ETS 300 826
Certifications	Law Valtaga Directive IECOEO
	Low Voltage Directive IEC950
	UL, CSA, and CE Mark
Divisional Division Community	
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance
	LE Link Layer Ping
	LE Dual Mode



LE Link Layer

LE Low Duty Cycle Directed Advertising

LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan

BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full

LE Privacy 1.2 -Link Layer Privacy

LE Privacy 1.2 -Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2

Headset Profile (HSP)

Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

BT5.2

ESR9/10 Compliance

LE Advertisement Extensions

Channel Selection Algo

Limited High Duty Cycle Non-Connectable Advertising

2Mbps LE

LE Long Range

- 2. Check latest software/driver release for updates on supported security features.
- 3. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
- 4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).
- 5. Usage of the 6GHz band relies on Windows 11 Operating System support.



^{1.} Wi-Fi 6E requires a Wi-Fi 6E router, sold separately, to function in the 6GHz band. Availability of public wireless access points limited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available in countries where Wi-Fi 6E is supported. Wi-Fi 6E is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels.

Intal® AV211 Wi_Fi 6F + Rlug	tooth® 5.3 wireless card M.2 vPro® 160MHz CNVi WW WLAN¹
Wireless LAN Standards	IEEE 802.11a
Wileless LAN Stallualus	IEEE 802.11b
	IEEE 802.11g
	IEEE 802.11n
	IEEE 802.11ac
	IEEE 802.11ax
	IEEE 802.11d
	IEEE 802.11e
	IEEE 802.11h
	IEEE 802.11i
	IEEE 802.11k
	IEEE 802.11r
	IEEE 802.11v
Interoperability	Wi-Fi certified
Frequency Band	802.11b/g/n/ax
	• 2.402 – 2.482 GHz
	802.11a/n/ac/ax
	• 4.9 – 4.95 GHz (Japan)
	• 5.15 – 5.25 GHz
	• 5.25 – 5.35 GHz
	• 5.47 – 5.725 GHz
	• 5.825 – 5.850 GHz
	• 5.955 – 6.415 GHz
	• 6.435 – 6.515 GHz
	• 6.535 – 6.875 GHz
Data Batas	• 6.895 – 7.115 GHz
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps
	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11n: max 300Mbps
	• 802.11ac: 1733Mbps
	• 802.11ax: max 2.4Gbps
Modulation	Direct Sequence Spread Spectrum
	OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
	, 1024QAM
Security ²	• IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only
	AES-CCMP: 128 bit in hardware
	802.1x authentication
	• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
	WPA2 certification
	WPA3 certification
	• IEEE 802.11i
	• WAPI
Network Architecture	Ad-hoc (Peer to Peer)
Models	Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power ³	• 802.11b: +17dBm minimum
	• 802.11g: +16dBm minimum
	• 802.11a: +17dBm minimum
	• 802.11n HT20(2.4GHz): +14dBm minimum
	• 802.11n HT40(2.4GHz): +13dBm minimum
	• 802.11n HT20(5GHz): +14dBm minimum
	• 802.11n HT40(5GHz): +13dBm minimum



	• 802.11ac VHT80(5GHz): +10dBm minimum
	• 802.11ac VHT160(5GHz): +10dBm minimum
	• 802.11ax HE40(2.4GHz): +12dBm minimum
	• 802.11ax HE80(5GHz): +10dBm minimum
	• 802.11ax HE160(5GHz): +10dBm minimum
Power Consumption	• Transmit mode 2.0 W
	Receive mode 1.6 W
	• Idle mode (PSP) 180 mW (WLAN Associated)
	• Idle mode 50 mW (WLAN unassociated)
	Connected Standby 10mW
	Radio disabled 8 mW
Power Management	ACPI and PCI Express compliant power management
	802.11 compliant power saving mode
Receiver Sensitivity ⁴	•802.11b, 1Mbps: -93.5dBm maximum
	•802.11b, 11Mbps: -84dBm maximum
	• 802.11a/g, 6Mbps: -86dBm maximum
	• 802.11a/g, 54Mbps: -72dBm maximum
	• 802.11n, MCS07: -67dBm maximum
	• 802.11n, MCS15: -64dBm maximum
	• 802.11ac, MCS0(VHT80): -84dBm maximum
	• 802.11ac, MCS9(VHT80): -59dBm maximum
	• 802.11ac, MCS9(VHT160): -58.5dBm maximum
	•802.11ax, MCS11(HE40): -57dBm maximum
	•802.11ax, MCS11(HE80): -54dBm maximum
	•802.11ax, MCS11(HE160): -53.5dBm maximum
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure
	Two embedded dual band 2.4/5/6 GHz antennas are provided to the card to support WLAN
	MIMO communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm
	2. Type 1216: 1.67 x 12.0 x 16.0 mm
Weight	1. Type 2230: 2.8g
	2. Type 1216: 1.3g
Operating Voltage	3.3v +/- 9%
Temperature	Operating: 14° to 158° F (–10° to 70° C)
	Non-operating: –40° to 176° F (–40° to 80° C)
Humidity	Operating: 10% to 90% (non-condensing)
,	Non-operating: 5% to 95% (non-condensing)
Altitude	Operating: 0 to 10,000 ft (3,048 m)
	Non-operating: 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF; LED OFF – Radio ON
LLD receivity	
HP Integrated Module with Bluet	ooth 4.0/4.1/4.2/5.0/5.1/5.2 /5.3 wireless card Technology
HP Integrated Module with Bluet Bluetooth® Specification	4.0/4.1/4.2/5.0/5.1/5.2 /5.3 wireless card Technology 4.0/4.1/4.2/5.0/5.1/5.2/5.3 wireless card Compliant
Bluetooth® Specification Frequency Band	4.0/4.1/4.2/5.0/5.1/5.2/5.3 wireless card Compliant 2402 to 2480 MHz
Bluetooth® Specification Frequency Band	4.0/4.1/4.2/5.0/5.1/5.2/5.3 wireless card Compliant 2402 to 2480 MHz Legacy: 0~79 (1 MHz/CH)
Bluetooth® Specification Frequency Band Number of Available Channels	4.0/4.1/4.2/5.0/5.1/5.2/5.3 wireless card Compliant 2402 to 2480 MHz Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Bluetooth® Specification	4.0/4.1/4.2/5.0/5.1/5.2/5.3 wireless card Compliant 2402 to 2480 MHz Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH) Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps
Bluetooth® Specification Frequency Band Number of Available Channels	4.0/4.1/4.2/5.0/5.1/5.2/5.3 wireless card Compliant 2402 to 2480 MHz Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH) Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps BLE: 1 Mbps data rate; throughput up to 0.2 Mbps
Bluetooth® Specification Frequency Band Number of Available Channels	4.0/4.1/4.2/5.0/5.1/5.2/5.3 wireless card Compliant 2402 to 2480 MHz Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH) Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps BLE: 1 Mbps data rate; throughput up to 0.2 Mbps Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels
Bluetooth® Specification Frequency Band Number of Available Channels	4.0/4.1/4.2/5.0/5.1/5.2/5.3 wireless card Compliant 2402 to 2480 MHz Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH) Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps BLE: 1 Mbps data rate; throughput up to 0.2 Mbps



Technical Specifications – Networking

Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 9.5 dBm for BR and EDR.			
Power Consumption	Peak (Tx): 330 mW			
i over consumption	Cuk (17). 330 mw			
	Peak (Rx): 230 mW			
	Selective Suspend: 17 mW			
Bluetooth® Software Supported	Microsoft Windows Bluetooth Software			
Link Topology				
Power Management	Microsoft Windows ACPI, and USB Bus Support			
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249			
Power Management	ETS 300 328, ETS 300 826			
Certifications	N. H. D. H. IFFERD			
	Low Voltage Directive IEC950			
	UL, CSA, and CE Mark			
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance			
bluetooth Florites Supported	LE Link Layer Ping			
	LE Dual Mode			
	LE Link Layer			
	LE Low Duty Cycle Directed Advertising			
	LE L2CAP Connection Oriented Channels			
	Train Nudging & Interlaced Scan			
	BT4.2 ESR08 Compliance			
	LE Secure Connection- Basic/Full			
	LE Privacy 1.2 – Link Layer Privacy			
	LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension			
	FAX Profile (FAX)			
	Basic Imaging Profile (BIP)2			
	Headset Profile (HSP)			
	Hands Free Profile (HFP)			
_	Advanced Audio Distribution Profile (A2DP)			
	BT5.2			
	ESR9/10 Compliance			
	LE Advertisement Extensions			
	Channel Selection Algo			
	Limited High Duty Cycle Non-Connectable Advertising			
	2Mbps LE			
	LE Long Range			

- 1. Wi-Fi 6E requires a Wi-Fi 6E router, sold separately, to function in the 6GHz band. Availability of public wireless access points limited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available in countries where Wi-Fi 6E is supported. Wi-Fi 6E is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels.
- 2. Check latest software/driver release for updates on supported security features.
- 3. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
- 4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).
- 5. Usage of the 6GHz band relies on Windows 11 Operating System support.



Technical Specifications – Input/Output Devices

I/O DEVICES

Physical Characteristics	Keys	104, 105, 106, 107, 109 layout (depending upon country)	
	Dimensions (L x W x H)	171.97 x 68.35 x 8.27 in (436.8± 1.5 x 137.6± 1.0 x 21.0± 1.0 cm)	
	Weight	1.32 lb (0.6± 0.08 kg)	
Electrical	Operating voltage	4.4-5.25VDC	
	Power consumption	50-mA maximum (with 5 VDC power supplied and three LEDs ON)/	
	System interface	USB or PS/2	
	ESD	Contact Discharge: 2, 4,6,8KV Air Discharge: 2, 4, 8,10,12.5KV	
	EMI – RFI	Conforms to FCC rules for a Class B computing device	
1echanical	Keycaps	Low-profile design	
	Switch actuation	60±12.5g nominal peak force with tactile feedback	
	Switch life	10 million keystrokes (Life tester)	
	Switch type	Contamination-resistant switch membrane	
	Key-leveling mechanisms	For all double-wide and greater-length keys	
	Cable length	6 ft (1.8 m)	
invironmental	Acoustics	43-dBA maximum sound pressure level	
	Operating temperature	50° to 122° F (10° to 50° C)	
	Non-operating temperature	Minus 30 degress to 60 degress Celsius	
	Operating humidity	10% to 90% (non-condensing at ambient)	
	Non-operating humidity	20% to 80% (non-condensing at ambient)	
	Operating shock	40 g, six surfaces	
	Non-operating shock	80 g, six surfaces	
	Operating vibration	2-g peak acceleration	
	Non-operating vibration	4-g peak acceleration	
	Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence	
	Drop (in box)	30 in (76.2 cm) on concrete, 16-drop sequence	
Approvals	UL, FCC, CE Mark, TUV GS, VCCI	, BSMI, RCM, KCC	
Ergonomic compliance	ANSI HFS 100, ISO 9241-4, and TUVGS		



Physical Characteristics	Keys	104, 105, 109 layout (depending upon country)	
	Dimensions (L x W x H)	17.34 x 5.68 x 0.78in (440.6 x 144.5 x 1.98 cm)	
	Weight	1.32 lb (598g)	
Electrical	Operating voltage	5 VDC, +/-5%	
	Power consumption	100mA (All LED on)	
	System interface	USB Type A plug connector	
	ESD	Contact Discharge: 8 KV Air Discharge: 12.5 KV	
	EMI - RFI	Conforms to FCC rules for a Class B computing device	
1echanical	Keycaps	Low-profile design	
	Switch actuation	60±10g nominal peak force with tactile feedback	
	Switch life	10 million keystrokes (Life tester)	
	Switch type	Contamination-resistant switch membrane	
	Key-leveling mechanisms	For all double-wide and greater-length keys	
	Cable length	6 ft (1.8 m)	
invironmental	Acoustics	43-dBA maximum sound pressure level	
	Operating temperature	50° to 122° F (10° to 50° C)	
	Non-operating temperature	-22° to 140° F (-30° to 60° C)	
	Operating humidity	10% to 90% (non-condensing at ambient)	
	Non-operating humidity	20% to 80% (non-condensing at ambient)	
	Operating shock	40 g, six surfaces	
	Non-operating shock	80 g, six surfaces	
	Operating vibration	2-g peak acceleration	
	Non-operating vibration	4-g peak acceleration	
	Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence	
	Drop (in box)	30 in (76.2 cm) on concrete, 16-drop sequence	
Approvals	CE Marking, TUV, EAC, FCC, cUL	us/CSAus, ICES, RCM, VCCI, KCC, BSMI	
Ergonomic compliance	ISO 9241-4, TUVGS		

Physical Characteristics	Keys	104/105/107/109layout (depending upon country)	
	Dimensions (L x W x H)	436 x 138 x24.7 mm	
	Weight	471g	
Electrical	Operating voltage	5V +- 5%	
	Power consumption	50mA	
	System interface	USB Type A plug connector	
	ESD	Contact Discharge: 8 KV Air Discharge: 12.5 KV	
	EMI - RFI	Conforms to FCC rules for a Class B computing device	
Mechanical	Keycaps	Low-profile design	
	Switch actuation	55±10g nominal peak force with tactile feedback	
	Switch life	10 million keystrokes (Life tester)	
	Switch type	Contamination-resistant switch membrane	
	Key-leveling mechanisms	For all double-wide and greater-length keys	
	Cable length	1.8 m	
Environmental	Acoustics	43-dBA maximum sound pressure level	
	Operating temperature	50° to 122° F (10° to 50° C)	
	Non-operating temperature	-4° to 149° F (-20° to 65° C)	
	Operating humidity	10% to 95% (non-condensing at ambient)	
	Non-operating humidity	0% to 95% (non-condensing at ambient)	
	Operating shock	40 g, six surfaces	
	Non-operating shock	80 g, six surfaces	
	Operating vibration	2-g peak acceleration	
	Non-operating vibration	4-g peak acceleration	
	Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence	
	Drop (in box)	30 in (76.2 cm) on concrete, 16-drop sequence	
Approvals	UL, cUL, FCC, CE, TUV GS, VCCI,	BSMI, RCM, KCC, USB-IF, WHQL, EN/IEC 60601-1	
Ergonomic compliance	ANSI HFS 100, ISO 9241-4, and	I TUVGS	

HP 655 wireless Keyboard	I	
Physical Characteristics	Keys	104, 105, 107,109 layouts
	Dimensions (L x W x H)	16.86 x 4.55 x 0.71 in (428.22 x 115.47 x 18.06 mm)
	Weight	0.96 lb (435g)
Electrical	Operating voltage	3 VDC, +/-5%
	Power consumption	20 mA Max (All LED on)
	System interface	2.4GHz Wireless
	ESD	Contact Discharge: 8 KV Air Discharge: 15 KV
	EMI - RFI	Conforms to FCC rules for a Class B computing device
Mechanical	Keycaps	Plunger, 2.0 mm key travel
	Key actuation	60±10g nominal peak force with tactile feedback
	Key life	10 million keystrokes (Life tester)
	Key structure type	Rubber dome & Membrane
	Key-leveling mechanisms	For all double-wide and greater-length keys
Environmental	Operating temperature	50° to 122° F (10° to 50° C)
	Non-operating temperature	-22° to 140° F (-30° to 60° C)
	Operating humidity	10% to 90% (non-condensing at ambient)
	Non-operating humidity	20% to 80% (non-condensing at ambient)
	Operating shock	40 g, six surfaces
	Non-operating shock	80 g, six surfaces
	Operating vibration	2-g peak acceleration
	Non-operating vibration	4-g peak acceleration
	Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence
	Drop (in box)	30 in (76.2 cm) on concrete, 16-drop sequence
Approvals		RC, TRA, CASA, UA, EAC, CNC, ANATEL, NOM-NYCE SCT, IFETEL, TELEC, KC, MCMC, IDA, BSMI, NCC, DWLF&M, TP-BY, MOC
Ergonomic compliance	TUVGS	



HP Wired Desktop 320K Ko	eyboard			
Physical Characteristics	Keys	104, 105, 107	,109 layouts	
	Dimensions(L x W x H)	18.86*4.55*0.66 in (426.2 x 110.9 x 16.7 mm)		
	Weight	1.00 lb(452g)		
Electrical	Operating voltage	5 VDC, +/-5%		
	Power consumption	50 mA Max (A	ll LED on)	
	System interface	USB Port		
	ESD	Contact Discharge: 8 KV Air Discharge: 15 KV (Class B)		
	EMI - RFI		ndard EN 55022: 2006+A Part 15 Class B	1: 2007, Class B.
Mechanical	Keycaps	2.0mm +/-0.2	mm at 120gf Key travel	
Environmental	Operating temperature	10° C to 90° C		
	Non-operating temperature	-30° C to 95° (
	Operating humidity	N/A		
	Non-operating humidity	10% to 90% (non-condensing at ambient)		
	Operating shock	N/A		
	Non-operating shock	i. Half-Sine Shock – End-Use Handling, Non-Operational Sample size: 5pcs. Condition: Sample power off. Axis: X, Y, Z axis (all 6 faces) – sample normal mode of operation. Number of shocks: 1 shock/face. Pulse duration: < 3 ms Velocity change: 50lps (inch-per-second)- 65lps desired ii. Trapezoidal Shock- Transportation Environment, Non-Operational Sample size: 5pcs. Condition: Sample power off. Orientation: All six faces: Front, Rear, Left, Right, Bottom Top. Configuration: As intended for shipment Number of shocks: 1 shock/face. Minimum faired acceleration: 30G's. Test also at 40 and to find margin. Velocity change: 266lps (inch-per-second) for product margor 100 cm < 40lb.		cond)- 65lps desired. Environment, Non- eft, Right, Bottom, and at est also at 40 and 50G's
		Frequency (Hz)	Slope (dB/oct)	PSD (g²/Hz)
		5-350	0	0.0001
	Operating vibration	350-500	-6	-
		500	- (0 215)	0.00005
			(~0.21G _{nms}) Total Test time: 10 n	ninutes
	Non-operating vibration	Frequency (Hz)	Slope (dB/oct)	PSD (g²/Hz)

Ergonomic compliance	TUVGS			
Approvals	CB, CE, FCC, ICES, EAC, NO	CB, CE, FCC, ICES, EAC, NOM-NYCE SCT, RCM, BIS, VCCI, KC, BSMI		
	Drop (in box)	10 times drop surface. Drop Height: 9	_	orner and 3 edges on rigid
	Drop (out of box)	76cm on carp	et, six-drop sequence	
		500	-0	0.0039
		137-350 350-500	0 -6	0.008
		100-137	-6	-
		5.100	0	0.015

HP Wired Desktop 320M M	louse	
Physical Characteristics	Keys	Left/right key
	Dimensions(L x W x H)	4.09 x2.50 x 1.40 in (103.8x 63.4 x 35.5 mm)
	Weight	0.16 lb(72g)
Electrical	Operating voltage	5 VDC, +/-0.25V
	Power consumption	100 mA Max
	System interface	USB Port
	ESD	Contact Discharge: 8 KV Air Discharge: 15 KV (Class B)
	EMI - RFI	European Standard EN 55022: 2006+A1: 2007, Class B. FCC/CFR 47: Part 15 Class B
Mechanical	Keycaps	0.3mm key travel
	Key actuation	75±20g
	Key life	1million cycles
	Key structure type	Tact Switch
	Key-leveling mechanisms	N/A
Environmental	Operating temperature	10° to 90° C
	Non-operating temperature	-30° C to 95° C
	Operating humidity	N/A
	Non-operating humidity	10% to 90% (non-condensing at ambient)
	Operating shock	N/A



, ,	, ,			
	Non-operating shock	Sample size: 5 Condition: Sam Axis: X, Y, Z axi operation. Number of s Pulse durati Velocity cha ii. Trapezoidal Operational Sample size: 5 Condition: Sam Orientation: Al Top. Configuration: Number of sho Minimum faire to find margin. Velocity chang	pple power off. s (all 6 faces) – sample r hocks: 1 shock/face. on: < 3 ms nge: 50lps (inch-per-sec Shock- Transportation E pcs. uple power off. l six faces: Front, Rear, L As intended for shipmen cks: 1 shock/face. d acceleration: 30G's. Te	normal mode of ond)- 65lps desired. nvironment, Non- eft, Right, Bottom, and
		20 <m<40lb. Frequency (Hz)</m<40lb. 	Slope (dB/oct)	PSD (g²/Hz)
		5-350	0	0.0001
	Operating vibration	350-500	-6	-
		500	-	0.00005
			(~0.21G _{nms})	
		Total Test time: 10 minutes		
		Frequency (Hz)	Slope (dB/oct)	PSD (g²/Hz)
		5.100	0	0.015
	Non-operating vibration	100-137	-6	-
		137-350	0	0.008
		350-500	-6	-
		500	-	0.0039
	Drop (out of box)	76cm on carpet, six-drop sequence		
	Drop (in box)	N/A		
Approvals	CB, CE, FCC, cULus, ICES, EAC, NOM-NYCE SCT, RCM, VCCI, KC, BSMI			
Ergonomic compliance	TUVGS			

HP 655 wireless Mouse			
Dimensions (H x L x W)	4.74 x 2.75 x 1.63 in (120.29 x 69.97 x41.39 mm)		
Weight	0.194lb (88g)		
Environmental	Operating temperature	50° to 122° F (10° to 50° C)	
	Non-operating temperature	-22° to 140° F (-30° to 60° C)	
	Operating humidity	10% to 90% (non-condensing at ambient)	
	Non-operating humidity	20% to 80% (non-condensing at ambient)	
	Operating shock	40 g, six surfaces	
	Non-operating shock	80 g, six surfaces	
	Operating vibration	2-g peak acceleration	
	Non-operating vibration	4-g peak acceleration	
Electrical	Operating voltage	3 VDC, +/-5%	
	Power consumption (typical)	10 mA Max	
	Resolution	1,200 DPI (Default)	
	Sensor	Pixart PAW3222DB-TJDS	
	Tracking speed	10G(max), 1G=9.8m/s2	
	Tracking acceleration	2.4GHz Wireless	
Mechanical	Color	Jack Black	
Regulatory approvals	Compliant	CB, CE, FCC, cULus, ICES, IC, TRC, TRA, ICASA, UA, EAC, CNC, ANATEL, NOM-NYCE SCT, IFETEL, MPTC, RCM, PosTel, VCCI, TELEC, KC, MCMC, IDA, BSMI, NCC, DWLF&M, TP-BY, MOC	
Ergonomic compliance	Compliant	TUVGS	



HP PS/2 Mouse			
Dimensions (H x L x W)	4.53 x 2.48 x1.46 in (115.2x 63 x37 mm)		
Weight	0.22lb (101.6g)		
Environmental	Operating temperature	41° to 122° F (5° to 50° C)	
	Non-operating temperature	(-4° to 140° F)(-20° to 60° C)	
	Operating humidity	10% to 85% (non-condensing at ambient)	
	Non-operating humidity	5% to 95% (non-condensing at ambient)	
	Operating shock	40 g, six surfaces	
	Non-operating shock	80 g, six surfaces	
	Operating vibration	2-g peak acceleration	
	Non-operating vibration	4-g peak acceleration	
Electrical	Tracking speed	30 inch/sec (max)	
	Tracking acceleration	8G(max), 1G=9.8m/s2	
	System interface	PS/2	
Mechanical	Switch actuation	60±15g nominal peak force with tactile feedback	
	Switch life	3 million keystrokes (Life tester)	
	Switch type	Contamination-resistant switch membrane	
	Key-leveling mechanisms	For all double-wide and greater-length keys	
	Cable length	6 ft (1.8 m)	
	Color	Jack Black	
Regulatory approvals	Compliant	UL, FCC, CE Mark, TUV GS, VCCI, BSMI, RCM, KCC	



Dimensions (H x L x W)	112 x 63 x 36.2 mm (L x W x H)		
Weight	85 g		
Environmental	Operating temperature	50° to 122° F (10° to 50° C)	
	Non-operating temperature	-22° to 140° F (-30° to 60° C)	
	Operating humidity	10% to 90% (non-condensing at ambient)	
	Non-operating humidity	20% to 80% (non-condensing at ambient)	
	Operating shock	40 g, six surfaces	
	Non-operating shock	80 g, six surfaces	
	Operating vibration	2-g peak acceleration	
	Non-operating vibration	4-g peak acceleration	
lectrical	Operating voltage	5 VDC, +/-5%	
	Power consumption (typical)	100mA	
	Resolution	1,200 DPI	
	Sensor	Optical/ Laser USB mouse sensor	
	Tracking speed	30 inch/sec (max)	
	Tracking acceleration	8G(max), 1G=9.8m/s2	
1echanical	Connector	USB	
	Cable length	6 ft (1.8 m)	
	Color	Jack Black	
Regulatory approvals	Compliant	UL, FCC, CE Mark, TUV GS, VCCI, BSMI, RCM, KCC, EAC	



Technical Specifications – Audio/Multimedia

AUDIO/MULTIMEDIA

HP Pro Mini 400 G9 Desktop PC

Type Integrated

HD Stereo Codec Realtek ALC3252

Audio I/O Ports Front: Headset connector supports a CTIA and OMTP headset and is retaskable as a Line-in, Line-

out, Microphone-in or Headphone-out port

Internal Speaker Amplifier 2W class D mono amplifier for the internal speaker only. External speakers must be powered **Multi-streaming Capable**

Playback multi-streaming can be enabled in the audio control panel to allow independent audio streams to be sent to/from the front jacks or integrated speaker.

Supports resolutions from 16 to 24-bit; 44.1 kHz Sampling

to 192 kHz for DAC and ADC

Wavetable Syntheses Yes - Uses OS soft wavetable

Analog Audio Yes

of Channels on Line-Out Stereo (Left & Right channels)

Internal Speaker Yes

HP Pro SFF 400 G9 Desktop PC

Type Integrated

HD Stereo Codec Realtek ALC3252

Audio I/O Ports Front: Headset connector supports a CTIA and OMTP headset and is retaskable as a Line-in, Line-

out, Microphone-in or Headphone-out port

Rear: Audio line-in/line-out jack connector*, 3.5mm and support stereo output and retasking

Internal Speaker Amplifier 2W class D mono amplifier for the internal speaker only. External speakers must be powered Multi-streaming Capable

Playback multi-streaming can be enabled in the audio control panel to allow independent audio

streams to be sent to/from the front and rear jacks or integrated speaker.

Supports resolutions from 16 to 24-bit: 44.1 kHz to 192 kHz for DAC and ADC Sampling

Wavetable Syntheses Yes - Uses OS soft wavetable

Analog Audio Yes

of Channels on Line-Out Stereo (Left & Right channels)

Yes **Internal Speaker**

*NOTE: System default is line-out. Line-in / Line-out can be adjusted through the audio setting



Technical Specifications – Audio/Multimedia

HP Pro Tower 400/480 G9 PCI Desktop PC

Type Integrated

HD Stereo Codec Realtek ALC3252

Audio I/O Ports Front: Headset connector supports a CTIA and OMTP headset and is retaskable as a Line-in, Line-

out, Microphone-in or Headphone-out port

Rear: Audio line-in/line-out jack connector*, 3.5mm and support stereo output and retasking

Internal Speaker Amplifier Multi-streaming Capable

2W class D mono amplifier for the internal speaker only. External speakers must be powered Playback multi-streaming can be enabled in the audio control panel to allow independent audio

streams to be sent to/from the front and rear jacks or integrated speaker.

Supports resolutions from 16 to 24-bit; 44.1 kHz to 192 kHz for DAC and ADC

Wavetable Syntheses Yes - Uses OS soft wavetable

Analog Audio Yes

of Channels on Line-Out Stereo (Left & Right channels)

Internal Speaker Yes

*NOTE: System default is line-out. Line-in / Line-out can be adjusted through the audio setting

HP ProOne 440 G9 24 All-in-One PC

Type Integrated

HD Stereo Codec Realtek ALC3252

Audio I/O Ports Side 3.5mm headset connector supports an OMTP or CTIA style headset and is re-taskable as a

Line-in, Line-out, Microphone-in or Headphone-out port

Internal Speaker Amplifier 2W per channel class D stereo amplifier for the internal speakers only

Multi-streaming Capable Playback multi-streaming allows independent audio streams to be sent to/from the side jack and

integrated speakers.

Supports resolutions from 16 to 24-bit; 44.1 kHz to 192 kHz for DAC and ADC

Wavetable Syntheses Yes – Uses OS Soft Wavetable

Analog Audio Yes

of Channels on Line-Out Stereo (Left & Right channels)

Internal Speaker Yes - Stereo

INTEGRATED WEBCAM AND MICROPHONE

Optional integrated 5 MP RGB webcam & microphone; maximum resolution of 2592 x 1944 Optional integrated 5 MP RGB webcam with IR sensor & microphone; maximum resolution of 2592 x 1944



Technical Specifications – Power

POWER

	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
External Power Supplies ¹	90W EPS, active PFC, 88% average efficiency at 115V & 89% at 230Vac	N/A	N/A	120W EPS, active PFC, 88% average efficiency at 115V & 89% at 230Vac 150W EPS, active PFC, 88% efficiency in 115Vac / 89% efficiency in 230Vac 180W EPS, active PFC, 88% average efficiency at 115V & 89% at 230Vac 230W EPS, active PFC, 89% average efficiency at 115V / 230Vac
80 PLUS Gold	N/A	180W active PFC / 80 PLUS Gold 87/90/87% efficient at 20/50/100% load (115V) 90/92/89% efficient at 20/50/100% load (230V)	180W active PFC / 80 PLUS Gold 87/90/87% efficient at 20/50/100% load (115V) 90/92/89% efficient at 20/50/100% load (230V)	N/A
80 PLUS Platinum	N/A	240W active PFC / 80 PLUS Platinum 90/92/89% efficient at 20/50/100% load (115V) 91/93/90% efficient at 20/50/100% load (230V)	260W active PFC / 80 PLUS Platinum 400Wactive PFC / 80 PLUS Platinum 90/92/89% efficient at 20/50/100% load (115V) 91/93/90% efficient at 20/50/100% load (230V)	N/A
Operating Voltage Range	90Vac~264Vac	90Vac~264Vac	90Vac~264Vac	90Vac~264Vac
Rated Voltage Range	100Vac~240Vac	100Vac~240Vac	100Vac~240Vac	100Vac~240Vac
Rated Line Frequency	50HZ~60HZ	50HZ~60HZ	50HZ~60HZ	50HZ~60HZ
Operating Line Frequency	47HZ~63HZ	47HZ~63HZ	47HZ~63HZ	47HZ~63HZ
Rated Input Current with Energy Efficient* Power Supply	90W≦1.7A	180W Gold \leq 2.3A 240W Platinum \leq 2.9A	180W≦2.3A 260W≦3.1A 400W≦5.2A	120W≦1.7A 150W≦2.5A 180W≦2.5A 230W≦3.5A
DC Output	+19.5V	+12V	+12V	+19.5V
Current Leakage (NFPA 99: 2012)	Less than 500 microamps of leakage current at 264 Vac with the ground wire	microamps of leakage	Less than 500 microamps of leakage current at 264 Vac with	Less than 500 microamps of leakage current at 264 Vac with



Technical Specifications – Power

	disconnected, as required		the ground wire	the ground wire
	for Non-patient Electrical		disconnected, as	disconnected, as
	Appliances and	required for Non-	required for Non-	required for Non-
	• •	patient Electrical	patient Electrical	patient Electrical
		Appliances and	Appliances and	Appliances and
		Equipment used in a	Equipment used in a	Equipment used in a
	normal use. Per section	patient care facility or	patient care facility or	patient care facility or
	10.3.5.1.	that contact patients in	that contact patients in	that contact patients in
	Less than 100 microamps	normal use. Per section	normal use. Per section	normal use. Per section
	of leakage current at 264	10.3.5.1.	10.3.5.1.	10.3.5.1.
		Less than 100	Less than 100	Less than 100
	intact with normal	microamps of leakage	microamps of leakage	microamps of leakage
	polarity, as required for	current at 264 Vac with	current at 264 Vac with	current at 264 Vac with
	Non-patient Electrical	the ground wire intact	the ground wire intact	the ground wire intact
	Appliances and		with normal polarity, as	
	Equipment used in a	required for Non-	required for Non-	required for Non-
	patient care facility or	patient Electrical	patient Electrical	patient Electrical
	that contact patients in	Appliances and	Appliances and	Appliances and
	normal use. Per section	Equipment used in a	Equipment used in a	Equipment used in a
	10.3.5.1.	patient care facility or	patient care facility or	patient care facility or
				that contact patients in
			normal use. Per section	
		10.3.5.1.	10.3.5.1.	10.3.5.1.
Power Supply Fan	N/A	50mm variable speed	70mm variable speed	N/A
Power cord length*	6.0 ft. (1.83 m)	6.0 ft. (1.83 m)	6.0 ft. (1.83 m)	6.0 ft. (1.83 m)
Dimensions	90W: 126 x 50 x 30mm	200 x 85 x 53 mm	165 x 95 x 73 mm	120W: 138mm x
				68.5mm x 25.4mm
				150W: 148 x 75.5 x 25.
				4mm
				180W: 165.5mm x
				79mm x 25.4mm
				230W: 180mm x 88mm
_				x 25.4mm

^{1.} External power supplies, power cords, cables and peripherals are not low halogen. Service parts obtained after purchase may not be low halogen.



^{*}NOTE: 2m for India

HP Pro Series 400 G9 Desktops PCs

Technical Specifications – Power

The power supply shall comply with harmonic input current requirements as detailed in EN61000-3-2 and JEIDA MITI standards. The harmonic input current requirements must be met under the following operating conditions:

Load Requirements: 50% and 100%

Input Voltage: 230Vac/50Hz.

For active power factor correction the power factor at 50% &100% loads shall be greater than 0.9 over the entire nominal input voltage range (100-127VAC and 200-240VAC).

Condition	Standard Efficiency	82/85/82%	85/88/85%	87/90/87%	90/92/89%	Input Voltage
10% of Rated Load	-	75%	81%	84%	86%	115Vac/60HZ
20% of Rated Load	-	82%	85%	87%	90%	115Vac/60HZ
500/ of Doto 41 and	-	85%	88%	90%	92%	115Vac/60HZ
50% of Rated Load	PF>0.9	PF>0.9	PF>0.9	PF>0.9	PF>0.95	115Vac/60HZ
	PF>0.9	PF>0.9	PF>0.9	PF>0.9	PF>0.9	230Vac/50HZ
100% of Rated	70%	82%	85%	87%	89%	115Vac/60HZ
Load	PF>0.9	PF>0.9	PF>0.9	PF>0.9	PF>0.9	230Vac/50HZ



Technical Specifications – Weights and Dimensions

WEIGHTS & DIMENSIONS¹

	<u>DM</u>	<u>SFF</u>
Chassis (W x D x H)	6.97 x 6.89 x 1.35 in 177 x 175 x 34.2 mm	10.63 x 12.12 x 2.74 in 270 x 308 x 95 mm
System Volume	64 cu in 1.05 L	481.85 cu in 7.9 L
System Weight ¹	2.74 lb 1.25 kg	9.59 lb 4.35 kg
Max Supported Weight (desktop orientation)	N/A	77.16 lb 35 kg
Packaging Dimension (WxDxH)	19.57 x 5.04 x 8.78 in (497 x 128 x 223 mm)	15.52 x 19.65 x 8.07 in (394 x 499 x 205 mm)
	MPP* : 19.61 x 9.25 x 5.20 in (498 x 235 x 132 mm)	MPP* : 15.52 x 19.65 x 8.07 in (394 x 499 x 205 mm)
Shipping Weight	6.52 lb (2.97 kg)	15.31 lb (6.95 kg)
	MPP* : 7.50 lb (3.40 kg)	MPP* : 15.97 lb (7.25 kg)
Palletization Profile (Fabricated EPE)	18-units per layer 5 or 6 layers max depending on details of air freight 90 or 108 units per pallet depending on details of air freight	6-units per layer 11 layer max 66 per pallet 47.24 x 39.37 x 94.63 in, 1200 x 1000 x 2412 mm

1468 mm (including pallet)

Palletization Profile** (Molded Pulp)

10-units per layer 6-units per layer 10 to 19 layers max depending on 11 layer max details of freight 66 per pallet 100 or 190 units per pallet depending 47.24 x 39.37 x 94.63 in, 1200 x 1000 x on details of freight 2412 mm (including pallet)

45.354 x 39.13 x 57.80 in, 1152 x 994 x (including pallet)

46.26 x 39.21 x 103.74 in, 1175 x 996 x

2635 mm (including pallet)

1. Packaging material used will vary by country

2. Configured with 1 HDD & 1 ODD; DM configured with 1 HDD only

*NOTE: "Molded pulp paper" cushion.

**NOTE: The palletization is for single pack



Technical Specifications – Weights and Dimensions

TWR

Chassis (W x D x H) 6.1 x 12.13 x 13.27 in

155x 308 x 337 mm

System Volume 981.9 cu in

16.1 L

System Weight¹ 11.7 lb

5.31 kg

Max Supported Weight77.16 lb(desktop orientation)35 kg

Packaging Dimension 15.75 x 19.65 x 11.30 in (W x D x H) (400 x 499 x 287 mm)

MPP: 15.75 x 19.65 x 11.30 in (400 x 499 x 287 mm)

Shipping Weight 17.69 lb (8.03 kg)

MPP: 18.5 lb (8.4 kg)

Palletization Profile (Fabricated EPE) 6-units per layer

8 layer max 48 per pallet

47.24 x 39.37 x 95.12 in, 1200 x 1000 x

2416 mm (including pallet)

Palletization Profile (Molded Pulp) 6-units per layer

8 layer max 48 per pallet

47.24 x 39.37 x 95.12 in, 1200 x 1000 x

2416 mm (including pallet)

- 1. Packaging material used will vary by country
- 2. Configured with 1 HDD & 1 ODD; DM configured with 1 HDD only



Technical Specifications – Weights and Dimensions

ALL-IN-ONE DIMENSIONS¹

		Withou (VESA Co	t Stand ver Plate)	Cantilever Stand (Fixed Height Tilt Stand)		Adjustable l	Height Stand
		cm/kg	inch/lb	cm/kg	inch/lb	cm/kg	inch/lb
	Width	53.93 cm	21.23 in	53.93 cm	21.23 in	53.93 cm	21.23 in
	Length/Depth	8.96 cm	3.53 in	18.70 cm	7.36 in	22.5 cm	8.85 in
Product	Height	35.36 cm	13.92 in	40.28 cm	15.85 in	37.94 ~ 50.94 cm	14.93 ~ 20.05 in
	Weight	6.93 kg	15.28 lb	7.315 kg	16.12 lb	7.775kg	17.57 lb
	Width	66.0 cm	25.98 in	66.0 cm	25.98 in	66.0 cm	25.98 in
Package	Length/Depth	24.0 cm	9.45 in	24.0 cm	9.45 in	24.0 cm	9.45 in
rackage	Height	46.2 cm	18.19 in	46.2 cm	18.19 in	46.2 cm	18.19 in
	Weight	10.85 kg	23.92 lb	12.04 kg	26.54 lb	12.69 kg	27.98 lb
	Width	120.0 cm	47.24 in	120.0 cm	47.24 in	120.0 cm	47.24 in
	Length/Depth	100.0 cm	39.37 in	100.0 cm	39.37 in	100.0 cm	39.37 in
Palletization	Height	198.8 cm	78.27 in	198.8 cm	78.27 in	198.8 cm	78.27 in
for Sea/Rail	Weight	260.4 kg	574.08 lb	288.96 kg	663.96 kg	304.56 kg	671.52 lb
	Qty / Layer	6	5	6	5		6
	Layers	4	1		1		4
Qty / Pallet via		2	4	2		Ž	24
Qty / Pallet via	Air	1	8	1	8	1	8

^{1.} Packaging material used will vary by country.



^{2.} Configured with 1 HDD & 1 ODD.

^{3.} Package weight is based on EPE package.

^{4.} Actual system weight will depend on the system configuration.

Miscellaneous Features

MISCELLANEOUS FEATURES

Management Features

- Advanced Configuration and Power Management Interface (ACPI). Allows the system to wake from a low power mode.
 Controls system power consumption, making it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system.
- Intel® Wired for Management support; industry wide initiative to make Intel® architecture based PCs, servers and mobile computers more inherently manageable out-of-the-box and over the network
- Dual State Power Button; acts as both an on/off button and a suspend-to-sleep button

Serviceability Features

- Dual colored power LED on front of computer to indicate either normal or fault condition
- Diagnostic LED Explanation Table:
 - Power LED will blink red 2 to 5 times, then blink white 2 or more times, then repeat (with beep tones for each blink initially):
 - 2 red + 2 white User must provide file for BIOS recovery (USB storage typically)
 - 2 red + 3 white User must enter a key sequence to proceed with recovery by policy
 - 2 red + 4 white BIOS recovery is in progress
 - 3 red + 2 white Memory could not be initialized
 - 3 red + 3 white Graphics adaptor could not be found
 - 3 red + 4 white Power supply failure / not connected
 - 3 red + 5 white Processor not installed
 - 3 red + 6 white Current processor does not support an enabled feature
 - 4 red + 2 white Processor has exceeded its temperature threshold / system thermal shutdown
 - 4 red + 3 white System internal temperature has exceeded its threshold
 - 5 red + 2 white System controller firmware is not valid
 - 5 red + 3 white System controller detected BIOS is not executing
 - 5 red + 4 white BIOS could not complete initialization / mainboard failure
 - 5 red + 5 white System controller rebooted the system after a health or recovery timer triggered
- HP PC Hardware Diagnostics UEFI:
 - This utility enables hardware level testing outside the operating system on many components. The diagnostics can be invoked by pressing F2 at POST, and is available as a download from HP Support
- System/Emergency ROM
- Flash ROM
- CMOS Battery Holder for easy replacement
- Flash Recovery with Video Configuration Record Software
- 1 Aux Power LED on System PCA
- Processor ZIF Socket for easy Upgrade
- Over-Temp Warning on Screen (Requires IM Agents)
- DIMM Connectors for easy Upgrade
- Clear CMOS Button
- NIC LEDs (integrated) (Green & Amber)
- Dual Color Power and HD LED To Indicate Normal Operations and Fault Conditions
- Color coordinated cables and connectors
- Tool-less Hood Removal
- Front power switch
- System memory can be upgraded without removing the system board or any internal components
- Tool-less Hard Drive, memory & optical drive Removal (For MT, SFF, and DM only)
- Green Pull Tabs, and Quick Release Latches for easy Identification



HP Pro Series 400 G9 Desktops PCs

Miscellaneous Features

Additional Features	Description
Product Orientation	Microtower (MT) can be oriented in a tower (vertical) orientation. Small Form Factor (SFF) can be oriented as either a desktop (horizontal) or a tower (vertical) with optional vertical stand. Desktop Mini (DM) can be oriented as either a desktop (horizontal) or a tower (vertical) with optional vertical stand.
Boot Sectors Protection	MBR and GPT sectors of the hard drive are critical to booting the operating system. By saving the MBR or GPT data (depending on the how the OS was installed), the BIOS will be able to monitor for changes and allow the user to override them with the backup copy at boot-up.
Drive Protection System	DPS Access through F10 Setup during Boot
	A diagnostic hard drive self- test. It scans critical physical components and every sector of the hard drive for physical faults and then reports any faults to the user
	Running independently of the operating system, it can be accessed through a Windows-based diagnostics utility or through the computer's setup procedure. It produces an evaluation on whether the hard drive is the source of the problem and needs to be replaced
	The system expands on the Self-Monitoring, Analysis, and Reporting Technology (SMART), a continuously running systems diagnostic that alerts the user to certain types of failures
SMART Technology (Self-Monitoring, Analysis and Reporting Technology)	Allows hard drives to monitor their own health and to raise flags if imminent failures were predicted
SMART I - Drive Failure Prediction	Predicts failures before they occur. Tracks fault prediction and failure indication parameters such as re-allocated sector count, spin retry count, calibration retry count
SMART II - Off-Line Data Collection	By avoiding actual hard drive failures, SMART hard drives act as "insurance" against unplanned user downtime and potential data loss from hard drive failure
SMART III - Off-Line Read Scanning with Defect Reallocation	IOEDC: I/O Error Detection Circuitry
SMART IV - End-to-End CRC for hard drives	Detects errors in Read/Write buffers on HDD cache RAM



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After Market Options

AFTER MARKET OPTIONS

Graphics Solutions	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>	<u>Part Number</u>
NVIDIA T400 4GB GDDR6 3mDP		X	X		<u>5Z7E0AA</u>
AMD Radeon RX 6300 2GB DP HDMI		X	Х		<u>7Y6P7AA</u>
HP DisplayPort™ To HDMI True 4k Adapter	Х	X	Х	Х	2JA63AA
HP DVI Cable Kit		X	Х		DC198A
HP HDMI Standard Cable Kit	Х	X	Х	X	T6F94AA
HP DisplayPort™ Cable Kit	Х	X	X	Х	VN567AA
HP DisplayPort™ To VGA Adapter	Х	X	X	X	AS615AA
HP DisplayPort™ To DVI-D Adapter	Х	X	X	X	FH973AA

Desktop Mini Accessories	<u>Mini</u>	<u>SFF</u>	TWR	<u>AiO</u>	Part Number
HP Desktop Mini Port Cover v3	Х				13L69AA
HP Desktop Mini 2.5" SATA Drive Bay kit v2	X				13L70AA
HP Desktop Mini LockBox V2	Х				3EJ57AA
HP Desktop Mini DVD-Writer ODD Expansion Module	Х				K9Q83AA
HP Desktop Mini Security/Dual VESA Sleeve v3	X				13L67AA
HP Desktop Mini Security/Dual VESA Sleeve v3 With Power Supply Holder	х				13L68AA
HP B250 PC Mounting Bracket	Х				8RA46AA
HP B200 PC Mounting Bracket	X				762T5AA
HP B300 PC Mounting Bracket	X				2DW53AA
HP B300 PC Mounting Bracket with Power Supply Holder	х				7DB37AA
HP Desktop Mini Vertical Chassis Stand	Х				G1K23AA
B550 PC Mounting Bracket	Х				16U00AA
HP B560 PC Mounting Bracket	X				763U8AA
HP Quick Release Bracket 2	X				6KD15AA
HP Integrated Work Center Stand 5	Х		_		G1V61AA



HP Pro Series 400 G9 Desktops PCs

After Market Options

Data Storage Drives	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>	<u>Part Number</u>
HP PCIe Gen 4 NVME TLC M.2 512GB SSD	X	X	X	X	406L8AA
HP PCIe Gen 4 NVME TLC M.2 1TB SSD	X	X	X	X	406L7AA
HP 500GB 7200PRM SATA 6.0Gb/s 3.5" Hard Drive		X	X		QK554AA
HP 1TB 7200rpm SATA 6Gb/s 3.5" Hard Drive		X	X		QK555AA

Input Devices	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>	<u>Part Number</u>
HP Wired Desktop 320K Keyboard	Х	Х	X	X	9SR37AA
HP USB Business Slim CCID SmartCard Keyboard	Х	X	X	X	Z9H48AA
HP Wired Desktop 320MK Mouse and Keyboard	Х	Х	X	X	9SR36AA
HP Wired Desktop 320M Mouse	Х	Х	X	X	9VA80AA
HP 655 Wireless Keyboard and Mouse Combo	Х	Х	X	Х	4R009AA
HP 455 Programmable Wireless Keyboard	Х	Х	X	Х	4R177AA
HP 125 Wired Keyboard	Х	X	X	Х	266C9AA
HP 125 Wired Mouse	X	X	X	Х	265A9AA
HP 128 Laser Wired Mouse	х	Х	X	Х	265D9AA
HP 225 Wired Mouse and Keyboard Combo	Х	X	Х	Х	286J4AA
HP 225 Antimicrobial Wired Mouse and Keyboard Combo (China Only)	x	X	х	х	286K3AA

System Memory	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>	<u>Part Number</u>
HP 4GB DDR4-3200 UDIMM		X	X		13L78AA
HP 8GB DDR4-3200 UDIMM		X	X		13L76AA
HP 16GB DDR4-3200 UDIMM		X	X		13L74AA
HP 32GB DDR4-3200 UDIMM		Х	Х		13L72AA
HP 4GB DDR4-3200 SODIMM	Х			Х	13L79AA
HP 8GB DDR4-3200 SODIMM	Х			Х	13L77AA
HP 16GB DDR4-3200 SODIMM	Х			Х	13L75AA
HP 32GB DDR4-3200 SODIMM	X			Х	13L73AA

Multimedia Devices	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>	<u>Part Number</u>
HP S101 Speaker Bar		X	X		5UU40AA
HP Stereo 3.5mm Headset G2	Х	X	X		428K7AA
HP Stereo USB Headset G2		X	X		428K6AA

Communication Devices	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>	<u>Part Number</u>
Intel® Ethernet I225-T1 GbE NIC		Х	X		406L9AA



HP Pro Series 400 G9 Desktops PCs

After Market Options

Security Devices	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>	<u>Part Number</u>
HP Business PC Security Lock v3 Kit		Х	Х		3XJ17AA
HP Keyed Cable Lock 10mm	X	Х	Х	Х	T1A62AA
HP Master Keyed Cable Lock 10mm	Х	Х	Х	Х	T1A63AA

Stands and Mounting Accessories	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>	<u>Part Number</u>
HP B250 PC Mounting Bracket	Х				8RA46AA
HP B300 PC Mounting Bracket	Х				2DW53AA
HP B550 PC Mounting Bracket	Х				16U00AA
HP Quick Release Bracket 2	Х			X	6KD15AA
HP ProOne G9 VESA Plate with Power Supply Holder				X	56P78AA

I/O Devices	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>	<u>Part Number</u>
HP DisplayPort Port Flex IO v2	X	Х	X		13L54AA
HP HDMI Port Flex IO v2	X	X	Х		13L55AA
HP Type-C USB 3.1 Gen2 Port Flex IO v2		X	Х		13L59AA
HP Type-C USB 3.1 Gen2 Port with 100W PD Flex IO v2	X				13L60AA
HP VGA Port Flex IO v2	X	X	Х		13L53AA
HP Serial Port Flex IO 2nd	X				13L57AA
HP Internal Serial Port (400)			Х		3TK81AA
HP PCIe x1 Parallel Port Card		Х	Х		N1M40AA
HP 800/600/400 G3 Serial/ PS/2 Adapter		X	Х		1VD82AA
HP USB to Serial Port Adapter	X	Х	Х	X	J7B60AA
HP Serial Port Flex IO v3	X	X	X		5B895AA
HP USB-C To DisplayPort Adapter	X			x	N9K78AA
HP Single Mini Display Port Adapter to Display Port Adapter		Х	х		2MY05AA

NOTE: For more detail on HP I/O Devices please refer to the HP FLEX IO Option Cards QuickSpecs. URL is: http://h20195.www2.hp.com/v2/GetDocument.aspx?docname=c06042607

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HP Pro Series 400 G9 Desktops PCs

Change Log

Date	Version History	Action	Description of Change		
May 30, 2023	From v1 to v2	Update	T1000 8GB GDDR6 removed / All SSD specs tables corrected.		
June 5, 2023	From v2 to v3	Addition	Note added to RTX 3050 8GB GDDR6 Graphics Card		
June 27, 2023	From v3 to v4	Correction	Type-A SuperSpeed USB 5Gbps corrected to 1 for TWR, in "(1) Flexible Port 2" table		
July 3, 2023	From v4 to v5	Update	TWR 480 front call out image removed, title changed to have both platforms included.		
August 24, 2023	From v5 to v6	Update	(optional) added to Intel® Ethernet I225-T1 GbE NIC in N&C section		
September 11, 2023	From v6 to v7	Update	AMO updated.		
October 11, 2023	From v7 to v8	Addition	Intel® Core™ i5-13600T to Intel® 13th Generation Core™ Processors		
October 17, 2023	From v8 to v9	Update	EPEAT from Gold to Climate+		
October 20, 2023	From v9 to v10	Update	Mark checked for I219 on 400 G9 SFF & TWR on N/C first section		
	From v10 to v11				
	From v11 to v12				
	From v12 to v13				
	From v13 to v14				
	From v14 to v15				
	From v15 to v16				
	From v16 to v17				
	From v17 to v18				
	From v18 to v19				
	From v19 to v20				
	From v20 to v21				
	From v21 to v22				
	From v22 to v23				

